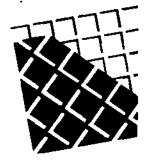
The Eighth Annual SEMICON/West Seminar: Status 1989

May 24 The Dunfey Hotel San Mateo, California



Sponsored by Dataquest's Semiconductor Equipment and Materials Service

Dataquest



Dd

The Eighth Annual SEMICON/West Seminar: Status 1989

The world semiconductor and semiconductor equipment industries have recently enjoyed healthy growth, but there are signs that both of these industries are slowing down. This year's seminar will present a snapshot of these industries as they are today along with Dataquest's forecasts for the next several years.

To accomplish this, Dataquest analysts will focus on the following topics:

- General industry outlook
- Electronic equipment demand
- Semiconductor demand
- ASICs as technology drivers
- A comparison of U.S. and Japanese fabs
- Worldwide capital spending
- Semiconductor equipment and materials trends
- Japanese semiconductor equipment market

This morning seminar will offer an opportunity for executives, strategic planners, R&D managers, and financial analysts to better understand the dynamically changing business environment of the semiconductor equipment and materials industries.

Agenda

Registration and Continental Breakfast-7-8 a.m.

- Welcome and Introduction
 - Joseph Grenier

Director

Semiconductor Equipment and Materials Service

- Semiconductor Demand: Forces, Forecast, and Fears
 - Mel Thomsen

Director

Strategic Analysis

■ Technology Drivers: Present and Future

Krishna Shankar

Industry Analyst

Semiconductor Equipment and Materials Service

■ A Comparison of U.S. and Japanese Fabs

Mark Reagan

Research Analyst Semiconductor Equipment and Materials Service

Break

Capital Spending and Capacity Utilization: Overcapacity?

George Burns

Industry Analyst

Semiconductor Equipment and Materials Service

■ Wafer Fab Equipment Industry—Status 1989

Joseph Grenier

Director

Semiconductor Equipment and Materials Service

Silicon Markets and Technology

Dr. Peggy Marie Wood

Industry Analyst

Semiconductor Equipment and Materials Service

Japanese Equipment Markets

Kaz Hayashi

Industry Analyst

Semiconductor Equipment and Materials Service/Japan

Adjourn

Seminar Information

Location

Dunfey San Mateo Hotel, 1770 South Amphlett Blvd. San Mateo, California 94402, telephone (415) 573-7661

Seminar Fees

Fees for the Semiconductor Equipment and Materials Service SEMICON/West Seminar are:

- Subscriber (or designee) from SEMS client company No Charge

Registration

■ The registration deadline is Friday, May 19, 1989.

Please register as soon as possible by completing in full and returning the registration form. Confirmation of your registration will be mailed to you. For attendees outside the United States, please include a fax or telex number for your confirmation.

Cancellation Policy

Cancellation deadline is May 19, 1989.

Registrants who either cancel after May 19, 1989, or who do not attend will be assessed a \$25 service charge unless they send a replacement. Notice of cancellation must be made to the Dataquest Conference Department, (408) 437-8245. You will be given a cancellation number when you call.

Reply Card

DEA INDIA	First	M.I
Tide		
Company		_
Street		
City	Suare Zi	P
Telephone ()	19ez	
□ SEMS client	Binderholder's name	
Client from any other Detacuest In	•	
Client from any other Detaquest In	Makery Science	Service
□ Client—FSP		
☐ Client—Prodential-Bache		
□ Noncliem company attendee		
☐ I cannot attend, but please send me Equipment and Materials Service	information on Dataquest'	s Semicondu <i>c</i> ion
■ Form of payment for con-	ference or proceeding	gs fees only:
☐ Check enclosed	☐ Money order enclosed	
Purchase order #		
□ Am. Express /	Exp. diate	
🗆 visa #	Exp. date	

Dataques

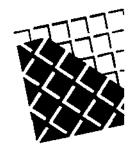
The Dun & Bradstreet Corporation

1290 Ridder Park Drive San Jose, California 95131-2398

Dataques

The acompany of the Dun's Bradstreet Com

1290 Ridder Park Drive San Jose, California 95131-2398



Annual SEMICON/West Seminar: Status 1989

Business Reply Mail

FIRST CLASS

PERMIT NO. 7279

SAN JOSE, CA

POSTAGE WILL BE PAID BY ADDRESSEE

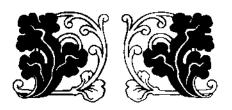
Dataquest Incorporated Attn: Conference Department (M.S. 1174) 1290 Ridder Park Drive San Jose, CA 95131-9980 NO POSTAGE NECESSARY IF MAILED IN THE UNITED STATES



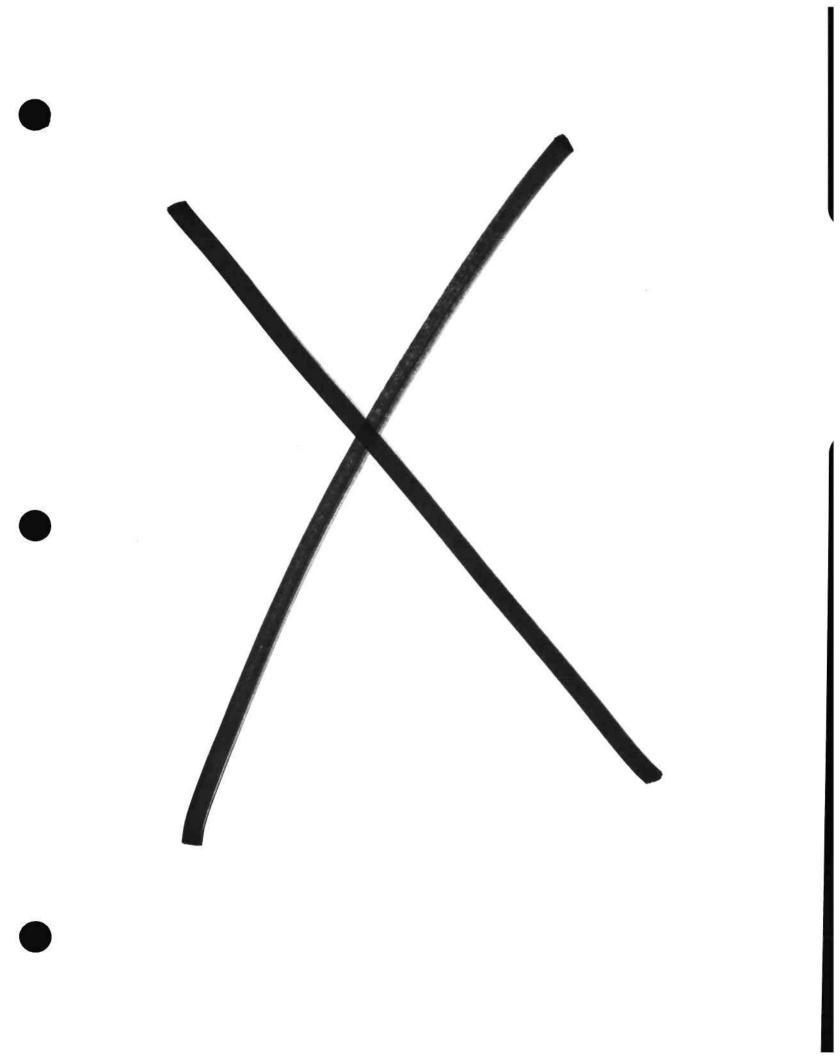
Semiconductor Equipment and Materials Service

The Eighth Annual SEMICON/West Seminar: Status 1989

Dataquest Incorporated



May 24, 1989 Dunfey San Mateo Hotel



Dataquest

The Dun & Bradstreet Corporation

SEMICON/West Seminar May 24, 1989 San Mateo, California

List of Attendees

AG Associates Donald M. Yoshikawa, Product Manage

ASM Epitaxy L. David Sikes, Vice President and

General Manager

ASM International N.V. Herbert Lakens, Director Marketing

Arthur H. del Prado, President and Chief

Executive Officer

ASM Lithography, Inc. Doug Marsh, Vice President, Worldwide

Sales

ASQ Technology, Inc. Steve Lee, President

ATEQ Corporation Georg Schacht, Marketing Manager

AVI Management Partners Eugene Flath, General Partner

Acer International Corporation Stephen Su, Vice President

Advanced Chemical Systems Richard Brewer, President & CEO

International Inc.

Advanced Mechanization, Inc. Richard Bayani, Marketing Manager Jerry Sesta, Engineering Manager

Advanced Micro Devices, Inc. C. Richard Deininger, Director,

Devices, Inc. C. Richard Deininger, Director,
Manufacturing Technology

Gary Heerssen, Vice President & Group Executive, Wafer Fabrication Ops Oolep Indreko, Director, Strategic

Technology Planning

Air Products & Chemicals, Inc. Mark Fitzgerald Dennis Peavler, Manager, Strategic Development Robert Shay, Manager, Electronics R&D Andre M. Williams, Marketing Manager Jeffrey D. Eagles, Manager, Electronic AIRCO Electronic Gases Business Team John P. Traub. Vice President Align-Rite International Plc. Greg Reyes, President and Chief American Semiconductor Equipment Executive Officer Tech. Anelva Corporation Fukuta Muneshige, Senior Program Manager, Planning Office Apple Computer, Inc. Tom Calderwood, Manager of Metrics & Standards Terry Kaspar, Procurement Manager: Memory Mary Segesta, Procurement Specialist: ROM Marty Walt Applied Materials Japan, Inc. Seisaku Takata, Assistant Manager Marketing Carol Bacchetti, Product Marketing Applied Materials, Inc. Engineer Peter Hanley, Vice President & General Manager, Etch Products Division Dennis Hunter, Director, Corporate Development

Applied Micro Circuits Corporation Donald E. Schrock, Vice President,
Operations

Grant Imper, Marketing Manager

Arthur Young & Company Alton D. Page,

Ashland Chemical Company	J. A. Duquin, VP & Gen Mgr, Electronic & Lab Products
Asyst Technologies, Inc.	Richard A. Darlow, Director, Marketing
Autoclave Engineers Inc.	Robert Brown, Chief Operating Officer Thomas Guelcher, Vice President Corporate Development, CFO
BTU Engineering Corporation	Peter H. Goebel, Vice President
Bandgap Technology Corporation	Dominique Cone, Market Analyst
Bank of America	Judy Sanchez, Vice President
Bank of the West	Marsha M. Poenisch, Vice President
Bechtel National, Inc.	William D. Blackwell, Technical Director Chris R. Kniel, Manager, Project Operations
Branson International Plasma Corporation	Lou Perrone, Vice President, Marketing & Technology
CTI-Cryogenics	Michael Grandinetti, Director of Sales
Cirrus Logic, Inc.	Michael Canning, Vice President, Manufacturing
Citicorp North America, Inc.	Kevin Nater, Account Officer
Cybeq Systems	Kanegi Nagai, General Manager
Daifuku U.S.A. Inc.	Sam Nakajima, Manager, Sales
Dexter Corporation	Larry Baxter, Marketing Manager, Powder Products

Kerry Grimes, Director of Marketing Dynachem Sales Neil Washburn, Development Specialist, E.I. DuPont de Nemours & Company Speciality Polym Sandra L. Bayless, Product Specialist ESI Gaylord Noblitt, Director, Marketing Eaton Corporation John Krukovski Electronic Manufacturing News Equitable Lomas Leasing Kim Atkins, AVP Vendor Program Steven Grundon, Vice President, Marketing Service Colleen Lusian. Assistant Vice President, Equipment Evaluation Ellie Sanchez, Market Research Manager Don Burkman, Vice President, Marketing & FSI International Development Walt Kalin, Director of Marketing Cindy Metzger, Marketing Communications Assistant Mary Jo Peters. Public Relations Coordinator Robert Selzer, Technical Director, GCA Corporation Advanced Applications Research. Development & Engineering GSIC Special Investments Jimmy Hsu, Assistant Director James Greed, Director, Technology General Signal Corporation Hiroshi Ishiwata, Sales & Marketing Manager

> Ron Dornseif, Director, Strategic Programs William W.R. Elder, President and Chief Executive Officer Robert McGeary, Director, SEMATECH & IBM Programs Ameeta Soni, Product Marketing Manager

Genus, Inc.

Gould AMI Semiconductors Joe O'Neill, Vice President, Sales Hampshire Instruments, Inc. Tom Kulczycki, Director, Sales & Marketing Moshe Lubin, President & CEO Dick Eichenseer, Commodity Manager Hewlett-Packard Company James K. Lee, Commodity Manager High Yield Technology Michele Klein, Vice President, Marketing Honeywell Microswitch Gary Tighe, Product Planner Chen Yong Lin, Process Manager Hualon Microelectronics Corporation Hyundai Electronics America H. K. Kim, Manager, Marketing Planning IVS, Inc. Hans F. Hoyer, President & CEO Insystems, Inc. Chris Billat, President Susan Billat, Vice President, Technology Development Anthony J. Carrozzo, National Sales Manager Intel Corporation Sarah Robinson, Senior Researcher Jacques J. Vuye, Manager, Strategic Research Group Italtel Franco Mammucari, Procurement Manager J. C. Schumacher Company Loren F. Sutherland, Director, Sales/Marketing JEOL Ltd. Tetsuyuki Itoh Kazuhiko Moriya, Section Manager

Semiconductor Equipment Division

KLA Instruments Corporation

Robert Boehlke, Executive Vice President George Duebner, Product Marketing Engineer C. Keith Van Sickle, Product Marketing Manager

Keithley Instruments, Inc.

Gary A. Pinkerton, Product/Market Manager John Snyder, Product/Market Manager

Kobe Development Corporation

Kazuo Ogata, General Manager Takeo Tanaka, Secretary General

Komatsu Silicon USA Inc.

Steven Kawamoto, Vice President

Kyocera America, Inc.

Chuck E. DeMars, Vice President, Microelectronics Division David Grooms, Product Manager, Microelectronics Group

L'Air Liquide

Jean-Pierre Brevignon, Corporate Liaison Officer Jean-Francois Piffard, Electronics Corporate Marketing Manager

LFE Corporation

Ronald Nickerson, General Manager

LTX Europe Ltd

Paul Scrivens, Director

Lam Research Corporation

Steve P. DeOrnellas, Vice President,
Marketing
Joe Monkowski, President, CVD Division
John Osborne, Senior Vice President,
Strategic Development
Bruce Rhine, Vice President, Marketing
CVD Division

Liquid Air Corporation

Susan Schmertmann, Product Manager, Alphagaz Division

J. S. Choo, Senior Managing Director Lucky Advanced Materials, Inc. S. K. Hahn, President Yasuhiko Morita, General Manager, Marubeni Hytech Co., Ltd. Semiconductor Equip Division Marubeni International Electronics Koichi Ando, Vice President William M. McMakin, President Micrion Corporation Microelectronics Technology Company Akira Miura, President & General Manager Chris Lavin, Product Manager Millipore Corporation James Ogg, Microelectronics Marketing Manager Gerald Y. Walle, Vice President & General Manager Don Tolliver, Contamination Manager Motorola Semiconductor, Inc. N. B. K. Corporation Dr. Kaz Augusa, Director, Quality Assurance Tetsho Miyhzhki, Philip Yin, Vice President, Sales & Marketing NCR Corporation Andy McKelvey, Division Director of Manufacturing **NEC** Corporation Ken Kunitomo, Director, Corporate Planning Group Shigemasa Hisatsugu, Managerial Staff, Nikon Corporation

Nikon Inc. Connie Hewitt, Regional Manager

Jack Isaacson, Field Sales Manager,

Hi-Tech Instruments

Takao Naito

Ind. Supplies & Equipment Division

Richard Fallon, Marketing Product Line Nikon Precision, Inc. Manager Murray Collette, President Oak Technical Inc. Joe Daltner, Director, Marketing Olin Hunt Specialty Products, Inc. Orasis Corporation Robert Welch, President, CEO Michael Solomon, General Manager Osaka Sanso Kogyo, Ltd. Eric Schiffer, Associate Oxford Partners Pall Ultrafine Filtration Corp Reed Sarver, Electronics Sales Manager Keen Kossoudji, Western Regional Perkin-Elmer Corporation Marketing Manager Charles Symborski, Director, Marketing Randall M. Young, Manager, Marketing · PlanTek Larry Campbell, Senior Vice President Plaser Corporation Behrooz Ataee. President & CEO Annette Adler, Senior Manager Price Waterhouse Technology Louise Claeys, Information Specialist Ellen Stover, Business Analyst Processing Technology (1988) Limited Rick B. Desbrisay, President

Prometrix Corporation Paul Covec, Director, Marketing

Prudential-Bache Capital Funding Mark Bode, Associate Account Officer

Prudential-Bache Securities Lou Gerkin, Managing Director Chad Keck, Managing Director

Marc E. Beckman, Purchasing Manager Quantum Corporation Lonnie Blackwell, Supplier Engineer Romano Ed, Buyer, Planner Huachen Chen, Analyst Rosenberg Capital Management Walter Price, Analyst Bruce W. Leister, National Account Ross-Dove Company, Inc. Executive Paul Kruger, Manager, Engineering SAMES Parker Brinson, Director, Sales and SEH America, Inc. Marketing Isao Iwashita, President Steve Harari, Vice President, Marketing Schlumberger Technologies North America Tonya Maudlin, Data Collection SEMI Administrator Semiconductor Systems Mark Siegel, President Gerry Leever, Marketing Manager SiSCAN Systems Singapore Economic Development Board Lit-Cheong Chong, San Francisco Center Director Software Express Craig Pilgrim, President & CEO Solid State Technology Magazine Sid Marshall, Editor

Taiwan Semiconductor Klaus C. Wiemer, President Manufacturing Corp.

Standard Microsystems Corporation

Sumitomo Eaton Nova Corporation

Frank Wanlass, Chief Scientist

Wagner Dean, Director

Craig Keith, Comptroller Tegal Corporation Corey J. Mullins, Marketing Manager Kazuhiko Nakamura, Executive Vice Tel America, Inc. President R. J. Hill, Director, Technology Temescal Raymond Phillips, Vice President, Tescon America Inc. Operations Akira Inoue, Senior Managing Director Tokyo Electron, Ltd. William Closser, President, CEO U.S. Semiconductor Corporation Ted Pappas, National Sales Manager ULVAC Randy O'Brien, Business Manager Union Carbide Corporation Union Carbide Industrial Gases Inc. William R. Couch, Senior Applications Engineer Bill Schmeh, Region Sales Manager Thomas L. Singman, Marketing Manager United Microelectronics Corporation Eric Chen, Product Planning Manager James Wu, Test Engineer Varian Extrion Michael Pippins, Product Manager Varian Associates Steve Jensen, General Manager, Thin Film Technology Thomas D. Sege, Chairman and Chief Executive Officer R. Bruce Thayer, Marketing Manager Veriflo Corporation Burt Lancaster, Vice President,

Marketing

Westech Systems, Inc.

Tom Tucker, President

Xynetics

Gordon C. Westwood, Vice President

Dataquest

a company of The Dun & Bradstreet Corporation

Dataquest



SEMICON/West Seminar May 24, 1989 San Mateo, California

List of Attendees

Annette Adler Price Waterhouse Technology

Koichi Ando Marubeni International Electronics

Behrooz Ataee Plaser Corporation

Kim Atkins Equitable Lomas Leasing

Kaz, Dr. Augusa N. B. K. Corporation

Carol Bacchetti Applied Materials, Inc.

Larry Baxter Dexter Corporation

Richard Bayani Advanced Mechanization, Inc.

Sandra L. Bayless ESI

Marc E. Beckman Quantum Corporation

Chris Billat Insystems, Inc.

Susan Billat Insystems, Inc.

Lonnie Blackwell Quantum Corporation

William D. Blackwell Bechtel National, Inc.

Mark Bode Prudential-Bache Capital Funding

Robert Boehlke KLA Instruments Corporation

Jean-Pierre Brevignon L'Air Liquide

Richard Brewer Advanced Chemical Systems Int'l Inc.

Parker Brinson SEH America, Inc.

Robert Brown Autoclave Engineers Inc.

Don Burkman FSI International

Tom Calderwood Apple Computer, Inc.

Larry Campbell PlanTek

Cirrus Logic, Inc. Michael Canning Anthony J. Carrozzo Insystems, Inc. Eric Chen United Microelectronics Corporation Huachen Chen Rosenberg Capital Management Lit-Cheong Chong Singapore Economic Development Board J. S. Choo Lucky Advanced Materials, Inc. Louise Claeys Price Waterhouse Technology William Closser U.S. Semiconductor Corporation Murray Collette Oak Technical Inc. Dominique Cone Bandgap Technology Corporation William R. Couch Union Carbide Industrial Gases Inc. Paul Covec Prometrix Corporation Joe Daltner Olin Hunt Specialty Products, Inc. Richard A. Darlow Asyst Technologies, Inc. Chuck E. DeMars Kyocera America, Inc. Steve P. DeOrnellas Lam Research Corporation Wagner Dean Sumitomo Eaton Nova Corporation C. Richard Deininger Advanced Micro Devices, Inc. Rick B. Desbrisay Processing Technology (1988) Limited Ron Dornseif Genus, Inc. George Duebner KLA Instruments Corporation J. A. Duquin Ashland Chemical Company

Airco Electronic Gases

Quantum Corporation

Jeffrey D. Eagles

Romano Ed

Dick Eichenseer

William W.R. Elder

Richard Fallon

Mark FitzGerald

Eugene Flath

Steven Francis

Lou Gerkin

Peter H. Goebel

Michael Grandinetti

James Greed

Kerry Grimes

David Grooms

Steven Grundon

Thomas Guelcher

S. K. Hahn

Peter Hanley

Steve Harari

Gary Heerssen

Connie Hewitt

R. J. Hill

Shigemasa Hisatsugu

Hans F. Hoyer

Jimmy Hsu

Dennis Hunter

Hewlett-Packard Company

Genus, Inc.

Nikon Precision, Inc.

Air Products & Chemicals, Inc.

AVI Management Partners

Brent Chemicals International PLC

Prudential-Bache Securities

BTU Engineering Corporation

CTI-Cryogenics

General Signal Corporation

Dynachem

Kyocera America, Inc.

Equitable Lomas Leasing

Autoclave Engineers Inc.

Lucky Advanced Materials, Inc.

Applied Materials, Inc.

Schlumberger Technologies

Advanced Micro Devices, Inc.

Nikon Inc.

Temescal

Nikon Corporation

IVS, Inc.

GSIC Special Investments

Applied Materials, Inc.

Applied Materials, Inc. Grant Imper Advanced Micro Devices, Inc. Oolep Indreko Tokyo Electron, Ltd. Akira Inoue Nikon Inc. Jack Isaacson General Signal Corporation Hiroshi Ishivata JEOL Ltd. Tetsuyuki Itoh SEH America, Inc. Isao Iwashita Varian Associates Steve Jensen FSI International Walt Kalin Apple Computer, Inc. Terry Kaspar Steven Kawamoto Komatsu Silicon USA Inc. Prudential-Bache Securities Chad Keck Craig Keith Tegal Corporation Hyundai Electronics America H. K. Kim High Yield Technology Michele Klein Chris R. Kniel Bechtel National, Inc. Perkin-Elmer Corporation Keen Kossoudji Paul Kruger SAMES John Krukovski Electronic Manufacturing News Tom Kulczycki Hampshire Instruments, Inc. Ken Kunitomo NEC Corporation

Ken Kunitomo

NEC Corporation

Herbert Lakens

ASM International N.V.

Burt Lancaster

Veriflo Corporation

Chris Lavin

Millipore Corporation

James K. Lee

Hewlett-Packard Company

Steve Lee

Gerry Leever

Bruce W. Leister

Chen Yong Lin

Moshe Lubin

Colleen Lusian

Franco Mammucari

Doug Marsh

Sid Marshall

Tonya Maudlin

Robert McGeary

Andy McKelvey

William M. McMakin

David W. McMullen

Cindy Metzger

Akira Miura

Tetsho Miyhzhki

Joe Monkowski

Yasuhiko Morita

Kazuhiko Moriya

Corey J. Mullins

Fukuta Muneshige

Kanegi Nagai

Takao Naito

Sam Nakajima

ASQ Technology, Inc.

SiSCAN Systems

Ross-Dove Company, Inc.

Hualon Microelectronics Corporation

Hampshire Instruments, Inc.

Equitable Lomas Leasing Co.

Italtel

ASM Lithography, Inc.

Solid State Technology Magazine

Semiconductor Microelectronics Int'l

Genus, Inc.

NCR Corporation

Micrion Corporation

AMP Incorporated

FSI International

Microelectronics Technology Company

N. B. K. Corporation

Lam Research Corporation

Marubeni Hytech Co., Ltd.

JEOL Ltd.

Tegal Corporation

Anelva Corporation

Cybeq Systems

Nikon Corporation

Daifuku U.S.A. Inc.

Kazuhiko Nakamura

Kevin Nater

Ronald Nickerson

Gaylord Noblitt

Randy O'Brien

Joe O'Neill

Kazuo Ogata

James Ogg

John Osborne

Alton D. Page

Ted Pappas

Dennis Peavler

Lou Perrone

Mary Jo Peters

Raymond Phillips

Jean-Francois Piffard

Craig Pilgrim

Gary A. Pinkerton

Michael Pippins

Marsha M. Poenisch

Walter Price

Greg Reves

Bruce Rhine

Sarah Robinson

Ellie Sanchez

Tel America, Inc.

Citicorp North America, Inc.

LFE Corporation

Eaton Corporation

Union Carbide Corporation

Gould AMI Semiconductors

Kobe Development Corporation

Millipore Corporation

Lam Research Corporation

Arthur Young & Company

ULVAC

Air Products & Chemicals, Inc.

Branson International Plasma Corporation

FSI International

Tescon America Inc.

L'Air Liquide

Software Express

Keithley Instruments, Inc.

Varian Extrion

Bank of the West

Rosenberg Capital Management

American Semiconductor Equipment Tech.

Lam Research Corporation

Intel Corporation

Equitable Lomas Leasing Co.

Judy Sanchez

Reed Sarver

Georg Schacht

Eric Schiffer

Bill Schmeh

Susan Schmertmann

Donald E. Schrock

Paul Scrivens

Thomas D. Sege

Mary Segesta

Robert Selzer

Jerry Sesta

Robert Shay

Mark Siegel

L. David Sikes

Thomas L. Singman

John Snyder

Michael Solomon

Ameeta Soni

Ellen Stover

Stephen Su

Loren F. Sutherland

Charles Symborski

Seisaku Takata

Takeo Tanaka

Bank of America

Pall Ultrafine Filtration Corp

ATEQ Corporation

Oxford Partners

Union Carbide Industrial Gases Inc.

Liquid Air Corporation

Applied Micro Circuits Corporation

LTX Europe Ltd

Varian Associates

Apple Computer, Inc.

GCA Corporation

Advanced Mechanization, Inc.

Air Products & Chemicals, Inc.

Semiconductor Systems

ASM Epitaxy

Union Carbide Industrial Gases Inc.

Keithley Instruments, Inc.

Osaka Sanso Kogyo, Ltd.

Genus, Inc.

Price Waterhouse Technology

Acer International Corporation

J. C. Schumacher Company

Perkin-Elmer Corporation

Applied Materials Japan, Inc.

Kobe Development Corporation

R. Bruce Thayer

Gary Tighe

Don Tolliver

John P. Traub

Tom Tucker

C. Keith Van Sickle

Jacques J. Vuye

Gerald Y. Walle

Marty Walt

Frank Wanlass

Neil Washburn

Robert Welch

Gordon C. Westwood

Klaus C. Wiemer

Andre M. Williams

James Wu

Philip Yin

Donald M. Yoshikawa

Randall M. Young

Arthur H. del Prado

Varian Associates

Honeywell Microswitch

Motorola Semiconductor, Inc.

Align-Rite International Plc.

Westech Systems, Inc.

KLA Instruments Corporation

Intel Corporation

Millipore Corporation

Apple Computer, Inc.

Standard Microsystems Corporation

E.I. DuPont de Nemours & Company

Orasis Corporation

Xynetics

Taiwan Semiconductor Mfg. Corp.

Air Products & Chemicals, Inc.

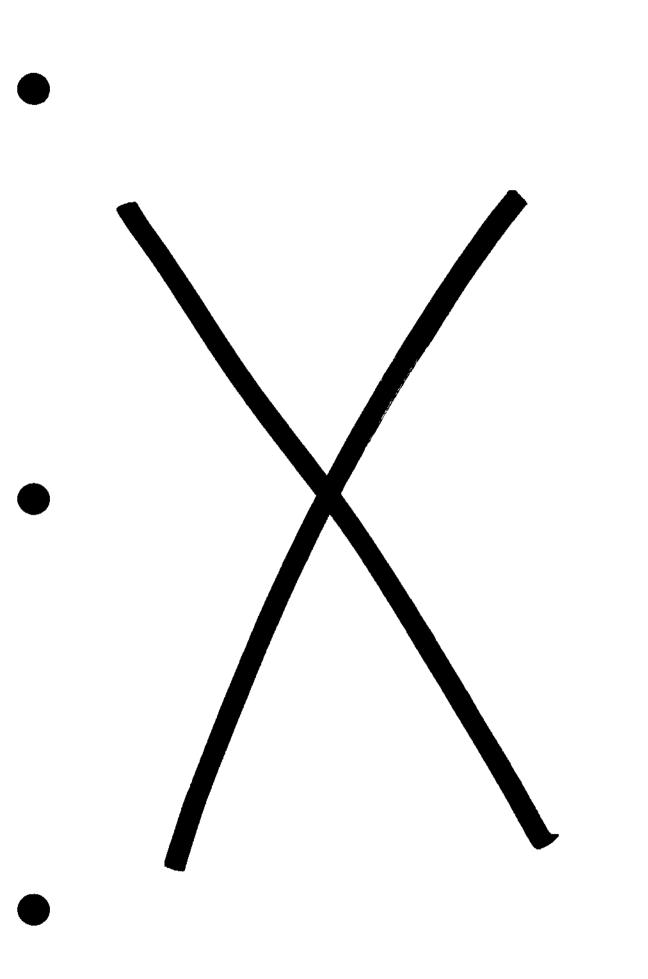
United Microelectronics Corporation

N. B. K. Corporation

AG Associates

Perkin-Elmer Corporation

ASM International N.V.





THE EIGHTH ANNUAL SEMICON/WEST SEMINAR: STATUS 1989

May 24, 1989 Dunfey San Mateo Hotel San Mateo, California

7:00 a.m. to

8:00 a.m.

Registration and Continental Breakfast

8:00 a.m.

Seminar Begins

Welcome and Introduction

Joseph Grenier

Director

Semiconductor Equipment and Materials Service

Dataguest Incorporated

Semiconductor Demand:

Forces, Forecast, and Fears

Mel Thomsen

Director

Strategic Analysis

Dataquest Incorporated

DRAMs and ASICs as Technology Drivers

Krishna Shankar

Industry Analyst

Semiconductor Equipment and Materials Service

Dataquest Incorporated

A Comparison of Japanese and U.S. Fabs

Mark T. Reagan

Industry Analyst

Semiconductor Equipment and Materials Service

Dataquest Incorporated

Break

(Continued)

Capital Spending:
Stability Achieved
George Burns
Industry Analyst
Semiconductor Equipment and Materials Service
Dataquest Incorporated

Wafer Fab Equipment Industry Status 1989
Joseph Grenier
Director
Semiconductor Equipment and Materials Service
Dataquest Incorporated

Silicon Wafers:
Existing Markets and Future Opportunities
Dr. Peggy Marie Wood
Industry Analyst
Semiconductor Equipment and Materials Service
Dataquest Incorporated

Japanese Equipment Markets
Kaz Hayashi
Industry Analyst
Semiconductor Equipment and Materials Service
Dataquest Japan Limited

12:00 Noon Adjourn

Dataquest

a company of The Dun & Bradstreet Corporation

Dataquest



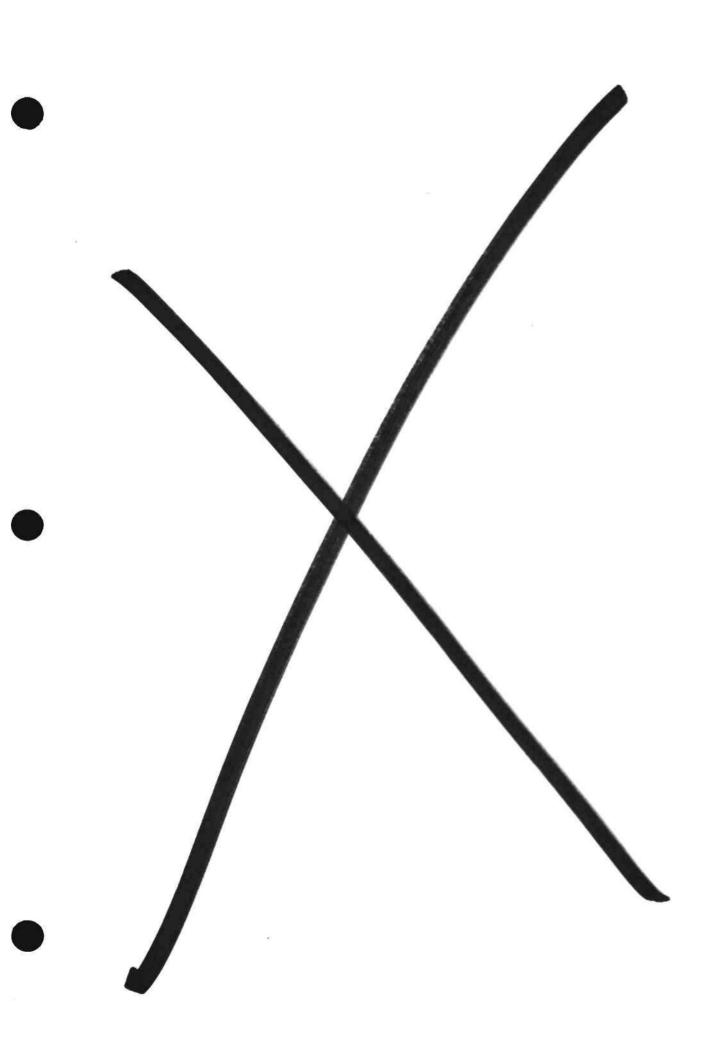
1989 SEMICON/WEST SEMINAR QUESTIONNAIRE

In order to continually improve the Semiconductor Equipment and Materials SEMICON/West Seminar, we need to better understand your information needs. Please help us by completing the following questionnaire. We would appreciate it if you would list your company name

	
1.	Is your company a Dataquest client?YesNo
2.	Which of the following best describes your company's primar activities?
	Semiconductor manufacturer
	Semiconductor equipment supplier
	Semiconductor materials supplier
	Other
	(Please specify)
3.	Which of the following best describes your position/title?
	CEO, President, Vice President
	Strategic Planning/Business Development
	Sales and Marketing Management
	Product Development/R&D/Engineering Management
	Other
	(Please specify)
4.	How did you learn about this seminar?
	The brochure was mailed directly to me
	Someone in my company gave me the brochure
	Someone from Dataquest called me
	Other
	(Please specify)

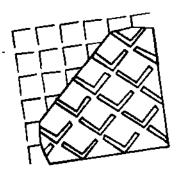
5.	Please list your main reasons for attending this seminar:							
		<u> Highest</u>			<u>Lowest</u>			
6.	How well did the seminar meet your objectives?	1	2	3	4	5		
7.	In the future, should the length of this seminarShorterIongerThe same?	be:						
8.	What speeches were the most important to you?							
	<u> </u>				_	_ _		
9.	What speeches were the least important to you?							
						–		
10.	Topics you would like to hear about at next year	's semi	ar:					
					_			
11.	Please use this space for your comments on any	aspect (of ou	ır se	emina	ır:		
					_			
	Name	 						
		(Opt	iona	al)				

•



\$305001, MIS (\$1000 51A)

Dataquest's Annual SEMICON/West Seminar May 24, 1989

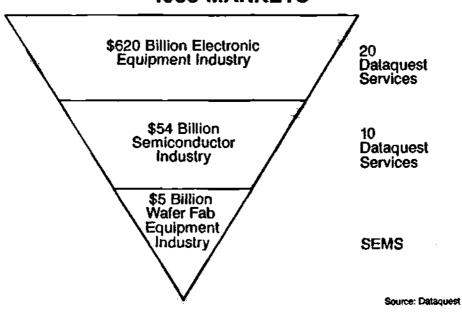


SEMICON/WEST SEMINAR 1989

JOSEPH GRENIER

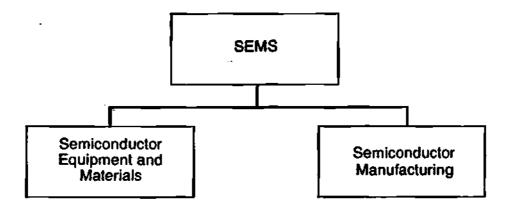
Director
Semiconductor Equipment and Materials Service
Dataquest Incorporated

ELECTRONICS INDUSTRY FOOD CHAIN 1988 MARKETS

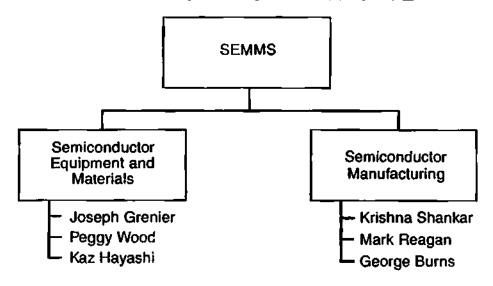


\$150000 BAG 05/15/80:GPE

SEMICONDUCTOR EQUIPMENT AND MATERIALS SERVICE



SEMICONDUCTOR EQUIPMENT, MATERIALS, AND MANUFACTURING SERVICE



\$305006.IMC 091980.GRE

AGENDA

- 1. Semiconductor Demand: Forces, Forecast, and Fears
- 2. Technology Drivers: Present and Future
- 3. A Comparison of U.S. and Japanese Fabs

Coffee Break

- 4. Capital Spending and Capacity Utilization: Overcapacity?
- 5. Wafer Fab Equipment Industry -- Status 1989
- 6. Silicon Markets and Technology
- 7. Japanese Equipment Markets

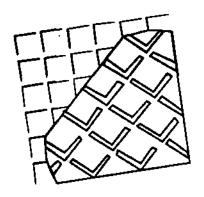
Adjourn

Dataquest

a company of The Dun & Bradstreet Corporation

CHITCHEN BAR PRESENT

Dataquest's Annual SEMICON/West Seminar May 24, 1989



SEMICONDUCTOR DEMAND: FORCES, FORECAST, AND FEARS

MEL THOMSEN
Director, Strategic Analysis
Dataquest Incorporated

SEMICONDUCTOR DEMAND: FORCES, FORECAST, AND FEARS

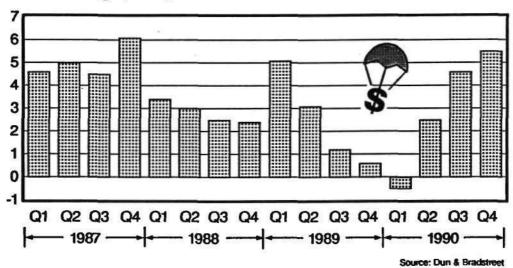
Forces

- Economic
- International trade
- Semiconductor industry trends
- Company performance
- Inventory levels

95153004 IMG 05/03/80:THU

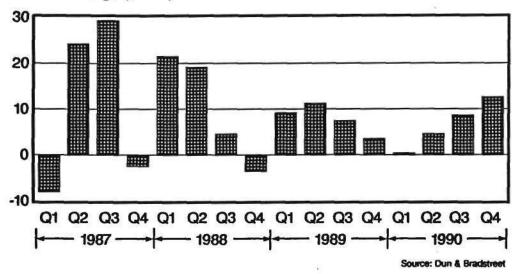
ESTIMATED UNITED STATES GNP GROWTH RATE

Percent Change (SAAR)



ESTIMATED CHANGE IN EQUIPMENT FIXED INVESTMENT

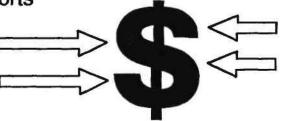
Percent Change (SAAR)



05153006 M/G 05/00/80:THO

ECONOMIC FORCES

- Slower U.S. growth, but no recession
- Most companies will maintain or increase capital spending
- Caution over higher interest rates
 - Higher cost of capital
 - Pressure on exports



SEMICONDUCTOR DEMAND: FORCES, FORECAST, AND FEARS

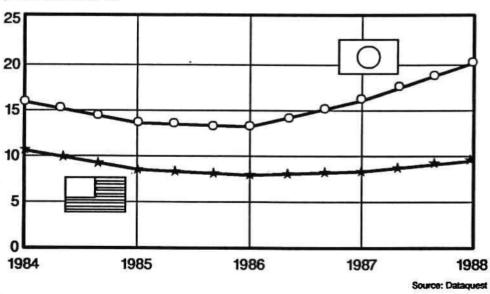
Forces

- Economic
- International trade
- Semiconductor industry trends
- Company performance
- Inventory levels

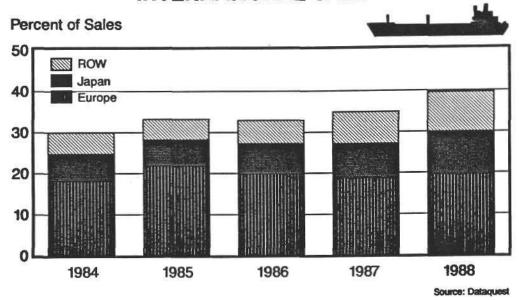
(OHT:98/00/80 DMI 80062189

THE MARKET SHARE BATTLE





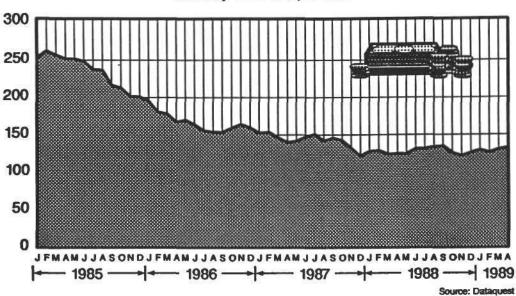
U.S. SEMICONDUCTOR INTERNATIONAL SALES



BS153010 RMG 05/03/89:THU

YEN-TO-DOLLAR EXCHANGE RATE

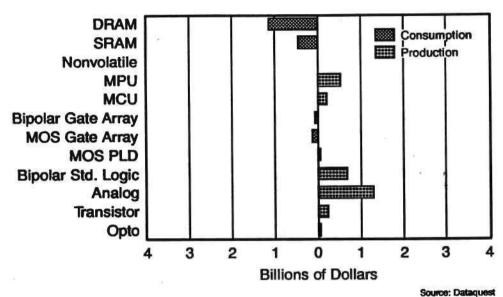
January 1985 to April 1989



© 1989 Dataquest Incorporated May 24 - Reproduction Prohibited

UNITED STATES SEMICONDUCTOR

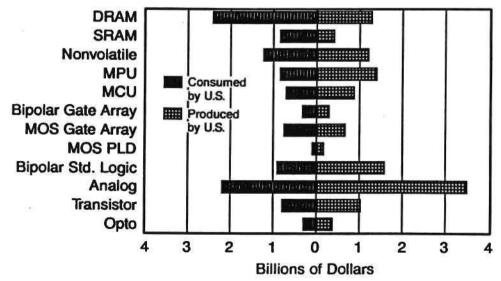
Difference between Consumption and Production



85153011 MG 05/04/89:THO

UNITED STATES SEMICONDUCTOR

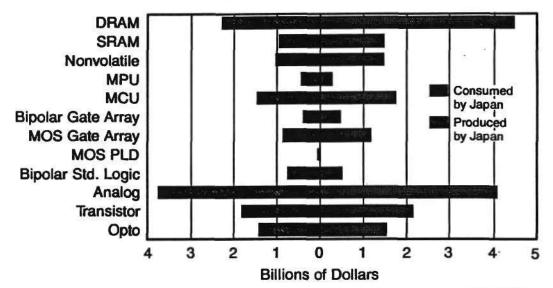
Consumption/Production Profile



Source: Dataquest

JAPANESE SEMICONDUCTOR

Consumption/Production Profile

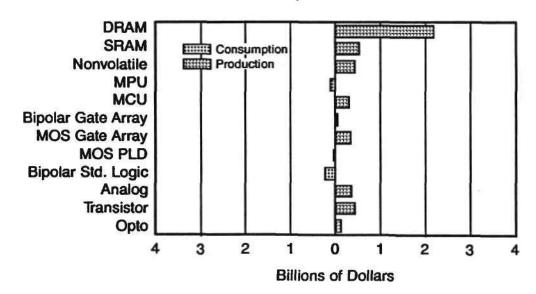


Source: Dataquest

B6153014.MG 05/04/69:THO

JAPANESE SEMICONDUCTOR

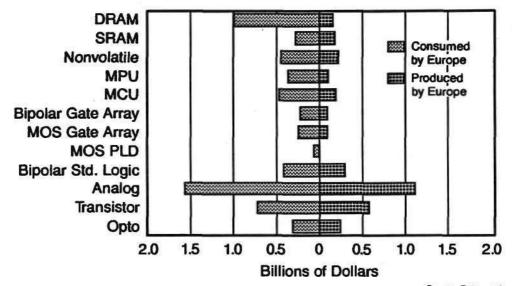
Difference between Consumption and Production



Source: Dataquest

EUROPEAN SEMICONDUCTOR

Consumption/Production Profile

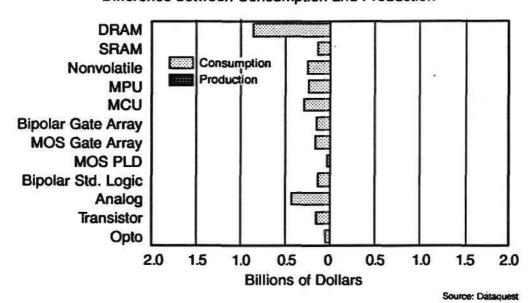


Source: Dataquest

98153016.MG 05/04/80:THO

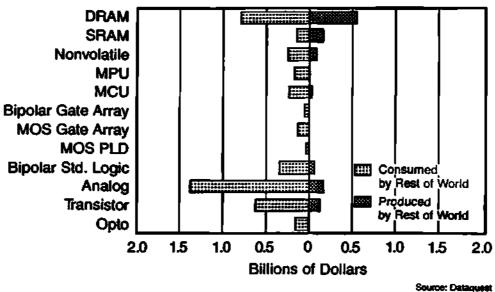
EUROPEAN SEMICONDUCTOR

Difference between Consumption and Production



REST OF WORLD SEMICONDUCTOR

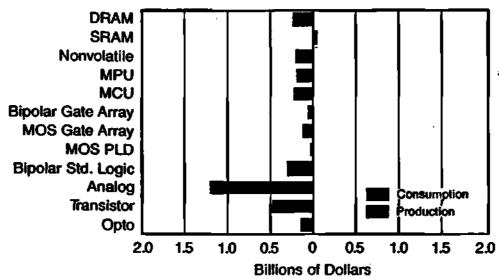
Consumption/Production Profile



MEISSEN NES GEGLASTRID

REST OF WORLD SEMICONDUCTOR

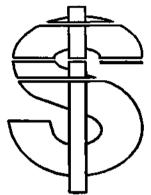
Difference between Consumption and Production



Source: Dataquest

WHERE DO THEY GET THEIR REVENUE?

North American Companies (Percent of 1988 Revenue)



9.6% ROW 19.7% Europe 10.4% Japan

60.4% North America

Source: Dataquest

SELECTION INC. CONTROL BACK

WHERE DO THEY GET THEIR REVENUE?

Japanese Companies (Percent of 1988 Revenue)



9.8% ROW 5.7% Europe

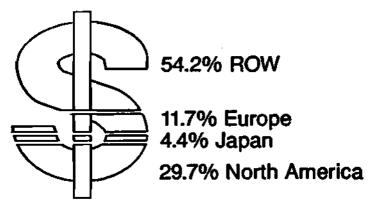
71.8% Japan

12.8% North America

Source: Dataquest

WHERE DO THEY GET THEIR REVENUE?

ROW Companies (Percent of 1988 Revenue)



Source: Dataquest

ESTENDED MAD GERCOME THAT

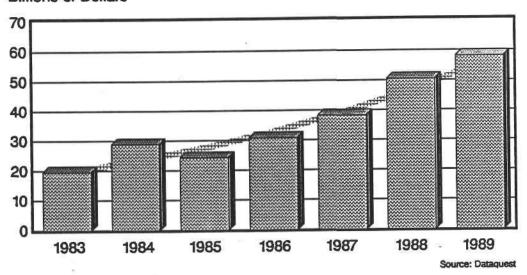
SEMICONDUCTOR DEMAND: FORCES, FORECAST, AND FEARS

Forces

- Economic
- International trade
- Semiconductor industry trends
- Company performance
- Inventory levels

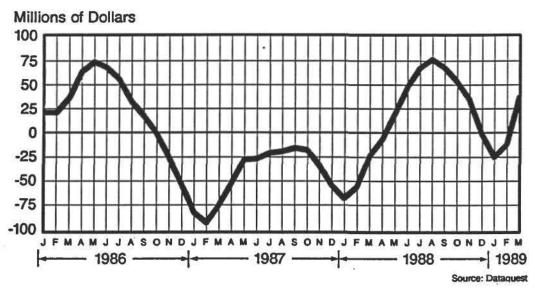
WORLDWIDE SEMICONDUCTOR SHIPMENT FORECAST

Billions of Dollars

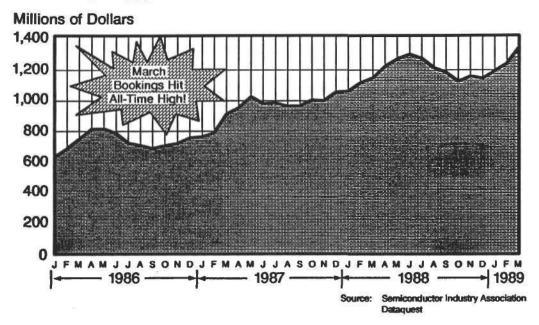


B5153027.IMG 05/05/89:THO

AVERAGE NORTH AMERICAN SEMICONDUCTOR SALES RELATIVE TO LONG-TERM TREND



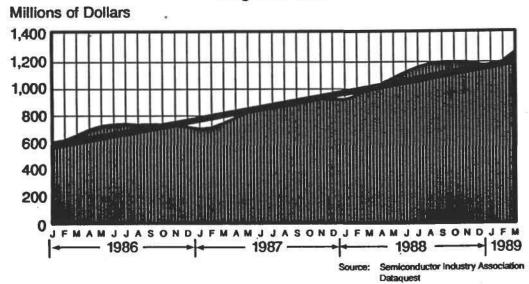
NORTH AMERICAN SEMICONDUCTOR THREE-MONTH AVERAGE BOOKINGS



85153026.MIG 05/03/89:THO

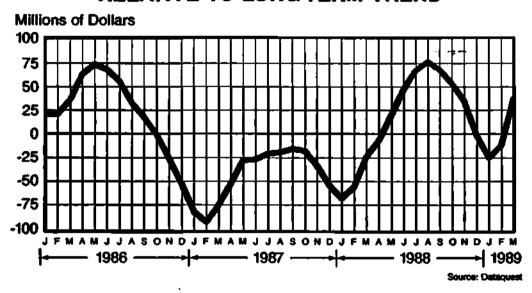
AVERAGE NORTH AMERICAN SEMICONDUCTOR SALES

Long-Term Trend



© 1989 Dataquest Incorporated May 24 - Reproduction Prohibited

AVERAGE NORTH AMERICAN SEMICONDUCTOR SALES RELATIVE TO LONG-TERM TREND



GE I ESCOSE MAC. GENOLOGO, THO

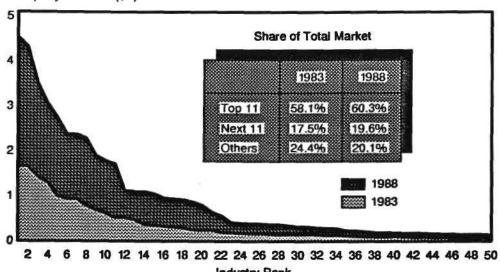
SEMICONDUCTOR DEMAND: FORCES, FORECAST, AND FEARS

Forces

- Economic
- International trade
- Semiconductor industry trends
- Company performance
- Inventory levels

CONCENTRATION OF POWER



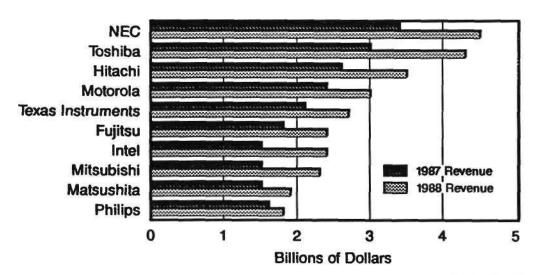


Industry Rank

Source: Dataquest

98153098.RM3 05/00/99:810

TOP 10 SEMICONDUCTOR COMPANIES' WORLDWIDE REVENUE



Source: Dataquest

SEMICONDUCTOR DEMAND: FORCES, FORECAST, AND FEARS

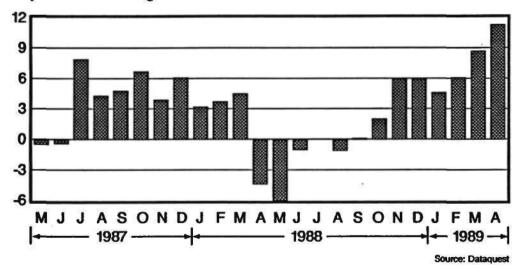
Forces

- Economic
- International trade
- Semiconductor industry trends
- Company performance
- Inventory levels

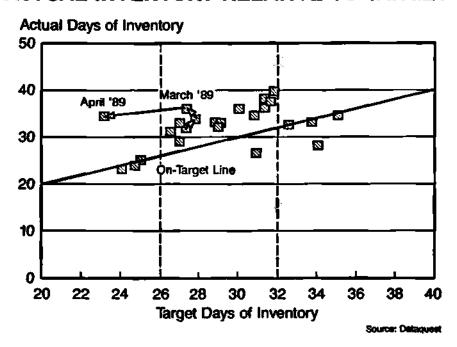
85153032 MG 05/03/89:THO

DAYS OF SEMICONDUCTOR INVENTORY FOR ALL USERS

Days Relative to Target



ACTUAL INVENTORY RELATIVE TO TARGET



DESIGNATION OF THE PARTY OF THE

SEMICONDUCTOR DEMAND FORCES, FORECAST, AND FEARS

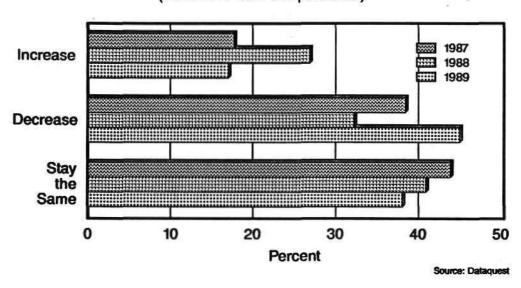
Forecast

- Buyers' expectations
- Important markets
- Emerging and fast-growing markets
- Semiconductor forecast
- Hot semiconductor products

95153040.MMG 05/03/MG:THO

BUYERS' EXPECTATIONS

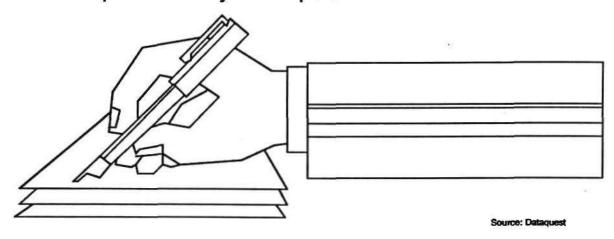
Expected Change in Target Inventory Levels (Percent of Total Respondents)



85153038.WG 08/03/80:THU

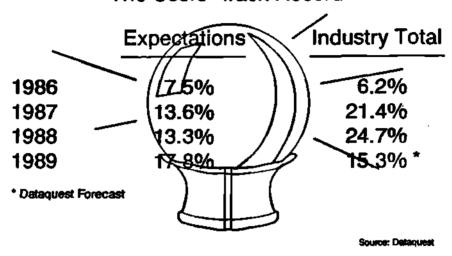
BUYERS' EXPECTATIONS

Users expect to increase semiconductor purchases by 17.8% percent in 1989



BUYERS' EXPECTATIONS





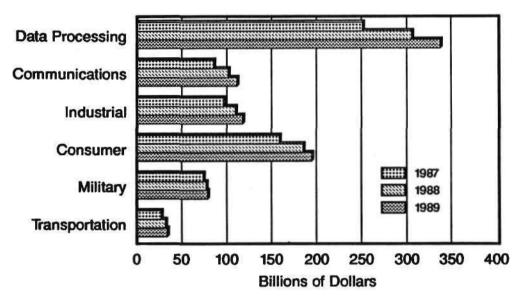
ES 153041 MAS OSAUSMED: THE

SEMICONDUCTOR DEMAND FORCES, FORECAST, AND FEARS

Forecast

- Buyers' expectations
- Important markets
- Emerging and fast-growing markets
- Semiconductor forecast
- Hot semiconductor products

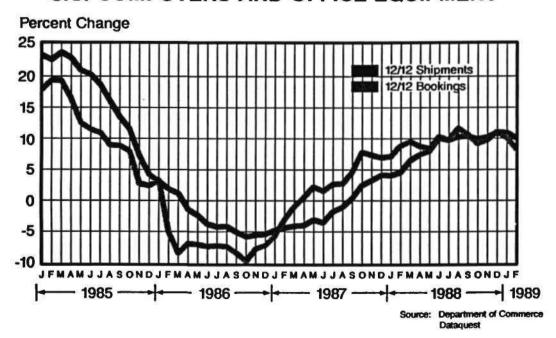
ESTIMATED WORLDWIDE ELECTRONICS MARKETS



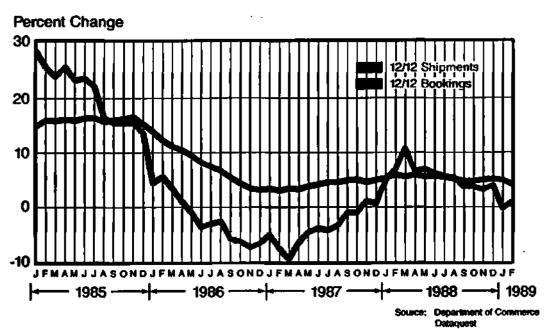
Source: Dataquest

85153043.MG 05/05/89:THO

U.S. COMPUTERS AND OFFICE EQUIPMENT

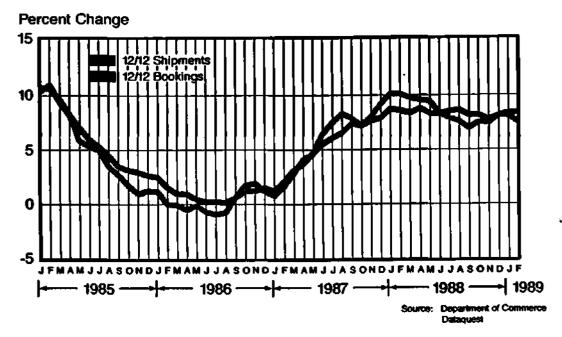


U.S. COMMUNICATIONS EQUIPMENT



BS153044 BMG CONDENSTRU

U.S. INSTRUMENTATION



SEMICONDUCTOR DEMAND FORCES, FORECAST, AND FEARS

Forecast

- Buyers' expectations
- Important markets
- Emerging and fast-growing markets
- Semiconductor forecast
- Hot semiconductor products

BETTER OF THE OF THE PARTY.

FASTEST-GROWING LARGE MARKETS

Estimated U.S. Revenue (Millions of Dollars)

Segment	<u>1988</u> ·	1992	CAGR
Processing Terminals	0.1	1.0	86.7%
Optical Disk Drives	0.4	3.0	61.8%
Electronic Publishing	1.6	6.6	42.4%
3- to 4-Inch Disk Drives	3.7	14.2	39.5%
Workstations	1.9	4.8	25.6%
Factory Networks	0.7	1.7	23.9%
LAN Connections	2.4	5.4	22.4%
Cellular Radio	3.6	7.9	21.9%
Voice Messaging Systems	0.5	15.8	137.2%
3.5-Inch Floppy Drives	1.1	17.5	99.7%

Source: Dataques

SEMICONDUCTOR DEMAND FORCES, FORECAST, AND FEARS

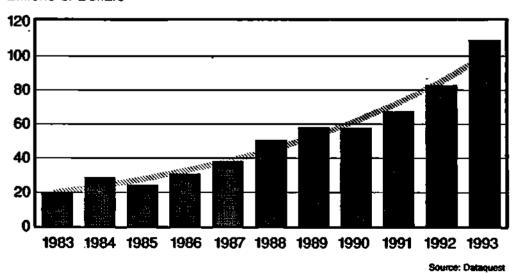
Forecast

- Buyers' expectations
- Important markets
- · Emerging and fast-growing markets
- Semiconductor forecast
- Hot semiconductor products

85153049-MIG 65/04/80:THU

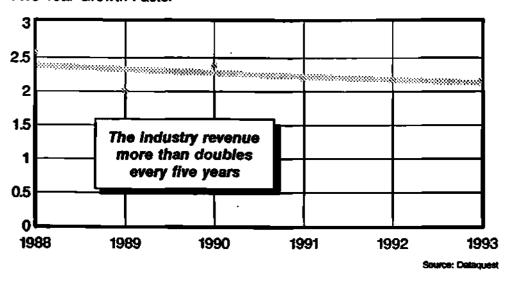
WORLDWIDE SEMICONDUCTOR SHIPMENTS HISTORY AND FORECAST

Billions of Dollars



WORLDWIDE SEMICONDUCTOR CONSUMPTION FIVE-YEAR FORECAST GROWTH PATTERN

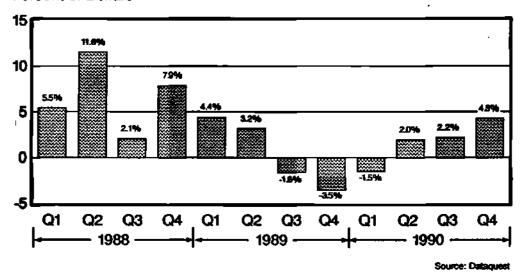
Five-Year Growth Factor



85163040,MG GE/64/80:THU

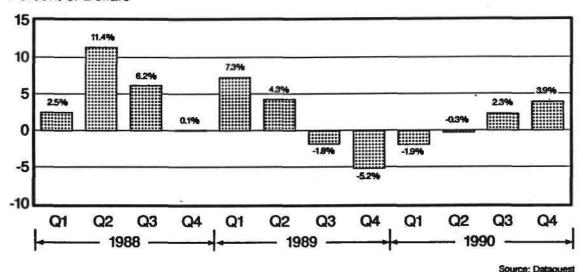
WORLDWIDE SEMICONDUCTOR CONSUMPTION QUARTER-TO-QUARTER GROWTH RATES

Percent of Dollars



NORTH AMERICAN SEMICONDUCTOR CONSUMPTION QUARTER-TO-QUARTER GROWTH FORECAST

Percent of Dollars



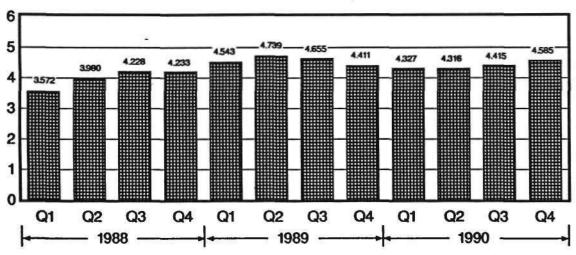
2

85153053.MG 05/04/89:THU

2 6 9

NORTH AMERICAN SEMICONDUCTOR CONSUMPTION QUARTERLY REVENUE FORECAST

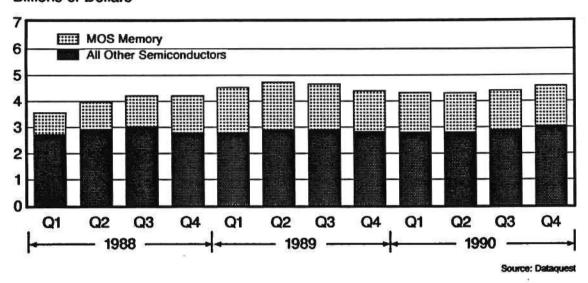
Billions of Dollars



Source: Dataquest

NORTH AMERICAN SEMICONDUCTOR CONSUMPTION QUARTERLY REVENUE FORECAST

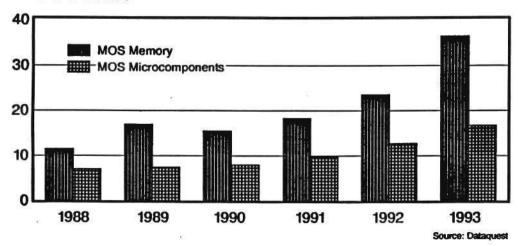
Billions of Dollars



(85153055.MG 05/04/89:THO)

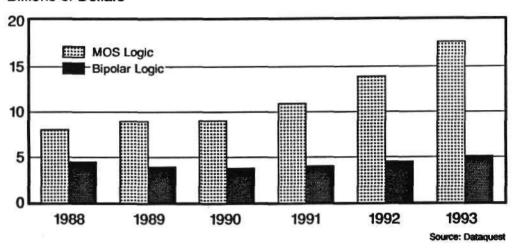
ESTIMATED WORLDWIDE SEMICONDUCTOR CONSUMPTION MOS MEMORY AND MICROCOMPONENTS

Billions of Dollars



ESTIMATED WORLDWIDE SEMICONDUCTOR CONSUMPTION MOS LOGIC AND BIPOLAR LOGIC

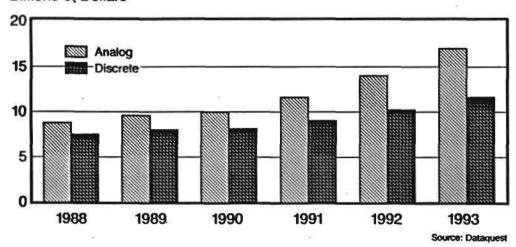
Billions of Dollars



85153057.MG 05/04/80:THU

ESTIMATED WORLDWIDE SEMICONDUCTOR CONSUMPTION ANALOG AND DISCRETE COMPONENTS

Billions of Dollars



SEMICONDUCTOR DEMAND FORCES, FORECAST, AND FEARS

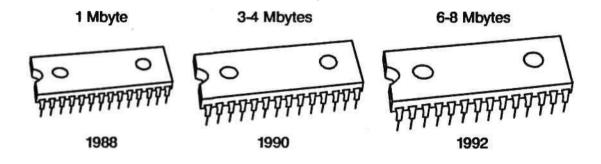
Forecast

- · Buyers' expectations
- Important markets
- Emerging and fast-growing markets
- Semiconductor forecast
- Hot semiconductor products

85153082.MG 05/03/80:THU

A DRAM-HUNGRY WORLD

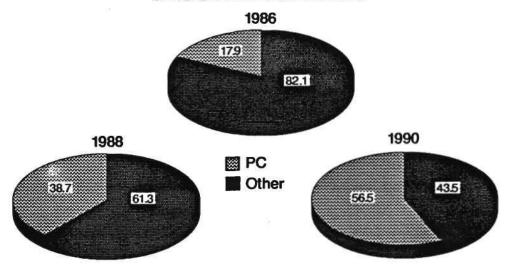
Worldwide PC Memory Content Forecast



(Average memory content for new PCs shipped in a particular year)

A DRAM-HUNGRY WORLD

Estimated PC DRAM Consumption as a Percentage of Worldwide DRAM Production



Source: Dataquest

85153063 MG 05/04/89 THO

HOT SEMICONDUCTOR PRODUCTS

(Millions of Dollars)

Product	1988	1992	CAGR
FIFO	56	142	26.2%
Video RAM	244	626	26.5%
Palette DACs	104	250	24.5%
High-Speed A/D Converters	115	260	22.6%
PC Chip Sets	397	775	18.2%
Switching Regulators	83	210	26.0%



Semiconductors with growth rates between 15 and 30 percent

Source: Dataquest

SUPER-HOT SEMICONDUCTOR PRODUCTS

(Millions of	Dollars)
--------------	----------

•		
1988	1992	CAGR
40	548	92.4%
25	332	91.8%
56	598	78.5%
177	971	53.0%
147	695	47.5%
148	547	38.6%
_	2,745	36.5%
65	214	34.9%
	40 25 56 177 147 148 835	40 548 25 332 56 598 177 971 147 695 148 547 835 2,745



Semiconductors with growth rates greater than 30 percent

Source: Dataquesi

0815300E.MAD 60/04/09:THU

CONCLUSIONS

- Long-term outlook (five years) is for aggressive growth
- Intermediate outlook (18 months) generally flat with some months slightly down. Computer market unsettled, causing great concern.
- Tighter inventory control and faster production cycles result in month-to-month variations in order rates
- Capacity generally not strained, resulting in high percentage of turns business
- Semiconductor manufacturers have low backlogs and low visibility to future business; consequently, cautious about future business

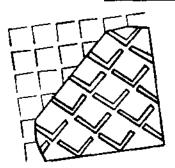
All things considered, the current semiconductor market environment is more like a road with rocks, ruts, and potholes going up a mountain rather than a smooth ride like falling off a cliff.

Dataquest

BB a company of The Dun & Bradstreet Corporation

86271001 MAG 06/10/00 SHA

Dataquest's Annual SEMICON/West Seminar May 24, 1989



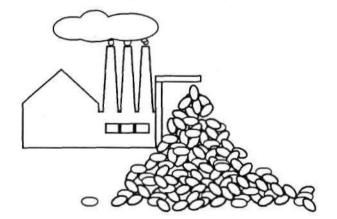
DRAMS AND ASICS AS TECHNOLOGY DRIVERS

KRISHNA SHANKAR

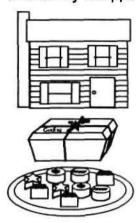
Industry Analyst
Semiconductor Equipment and Materials Service
Dataquest Incorporated

Is it easier to produce a million jelly beans than a box of Godiva chocolates?

The Jelly Bean Factory



The Candy Shoppe



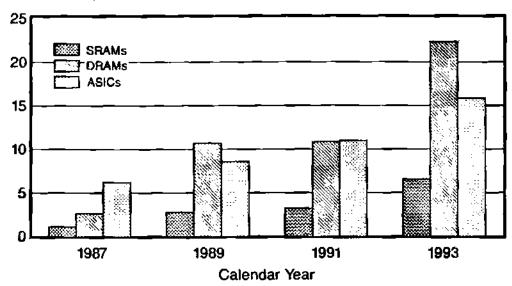
5271003 MG 05/10/89 SHA

AGENDA

- Memory and ASIC markets
- Industry structure
- Semiconductor technology drivers
- DRAM technology and process equipment
- ASIC technology and process equipment
- Special ASIC process innovations
- Fab configuration
- Synergy and convergence
- Conclusions

WORLD MEMORY AND ASIC MARKETS

Billions of Dollars



Source: Dataquest

85271006 64G 05/10/80 GHA

INDUSTRY STRUCTURE

DRAMs

- Capital intensive
- Oligopolistic structure
- Low product differentiation
- Vertically integrated companies
- One product per technology generation

ASICs

- Customer-service intensive
- Numerous competitors
- High product differentiation
- Small merchant companies and large captive companies
- Hundreds of low-volume products for each technology generation

TECHNOLOGY DRIVERS

DRAMs

- High volume/low cost
- Advanced device structures
- Submicron lithography
- "Hardwired" automation

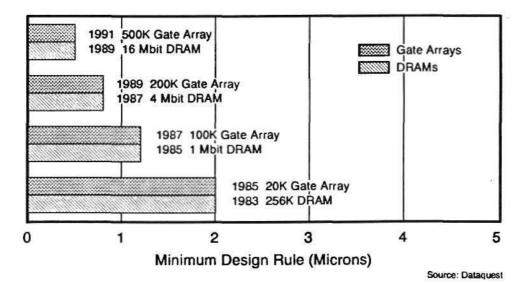
ASICs

- Low-volume/time to market
- Design automation
- Multilevel interconnect
- "Flexible" automation

B5271007.MG 05/10/80:SHA

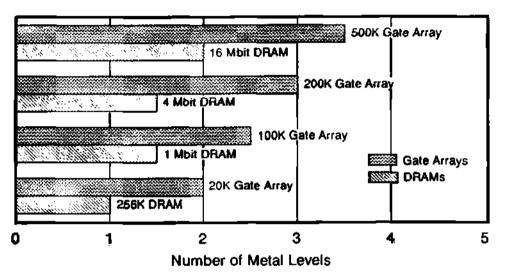
MINIMUM DESIGN RULES

Gate Arrays and DRAMs



"AVERAGE" INDUSTRY METAL LEVEL

Gate Arrays and DRAMs



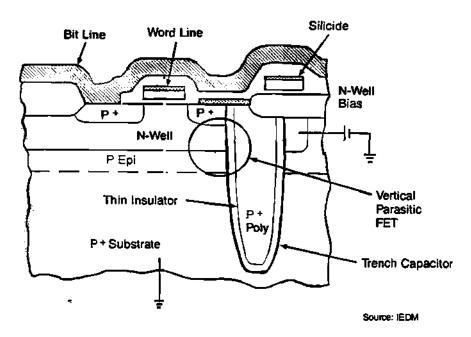
Source: Dataquest

54271000 BMC, (8,710/B) S1A

TYPICAL 4Mb DRAM TECHNOLOGY

Features .	Process/Equipment Needs
C High-quality EPI	Economical EPI process?
Retrograde wells	High-dose/high-energy implants
 Deep capacitor trenches 	High throughput, low RIE damage
 Stacked capacitor 	Conventional etch process
Oxide-nitride-oxide dielectric	Vertical furnace or RTP
Trench refill CVD oxide	TEOS conformal CVD reactors
0.8-micron gate length	Submicron capability steppers

PROCESS STRUCTURE FOR IBM's 4Mb DRAM



85271011.84G 06/10/00.84A

TECHNOLOGY FOR 200K TRIPLE-METAL ASIC GATE ARRAY

- Salicide
- Local interconnect
- Planarized CVD between metals

Feature

- Contact and VIA plugs
- Triple-metal interconnect
- Custom metallization option
- Many product configurations

Process/Equipment Need

RTP titanium silicide

RTP titanium nitride

Spin-on-glass planarization

or in-situ PECVD planarization

Tungsten CVD

High-resolution, defect-free

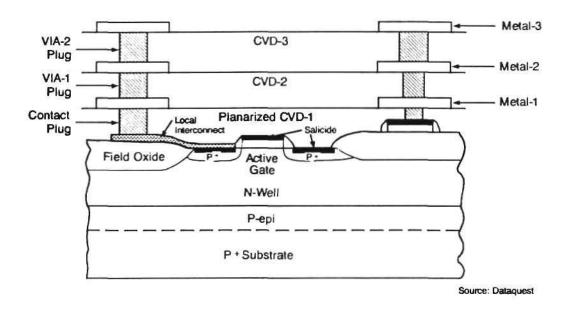
interconnect patterning

Flexible photoetch process

Quick-turn maskmaking;

good reticle management

FUTURE CMOS 200K TRIPLE-METAL ASIC GATE ARRAY



85271013 MIG 05/10/80 SHA

ASIC PROCESS AND EQUIPMENT INNOVATIONS

- Laser-based interconnect patterning; quick-turn ASICs
- Focused ion beam tungsten directwrite interconnects
- E-beam lithography for maskless, direct-write ASICs
- Single-wafer etching and deposition systems
- Steppers with elaborate reticle management
- Multiproduct, computer-integrated manufacturing

FAB CONFIGURATION

4Mb DRAM Fabs

- Maxifabs (\$150M-\$200M)
- High-volume, single product
- Dedicated automation
- Serial "assembly line"
- Fab organized by function
- High throughput, dedicated steppers for each layer
- Mix of batch and singlewafer processing

ASIC Fabs

- Minifabs (\$20M-\$50M)
- Low-volume, multiproduct
- Programmable automation
- Autonomous lines in parallel
- Fab organized by product
- Flexible steppers with low setup time
- Single-wafer processing equipment
- Portable/desktop fabs?

8271016.IMG 06/10/89:6HA

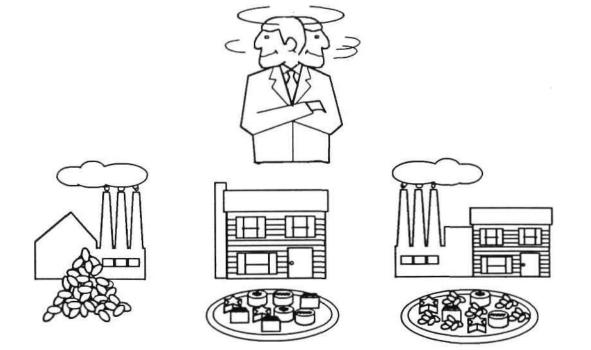
SYNERGY AND CONVERGENCE

- ASIC products with increasing on-chip SRAM memory
- Custom DRAMs and SRAMs for video, graphics applications
- Universal BiCMOS process for ASICs and high-speed SRAMs
- DRAM process trend toward 3-D silicon structure
- Multilevel interconnect technology now standard for ASIC and memory products
- Memory producers getting into ASIC manufacturing to balance fab capacity and offer one-stop shops
- · Modular, reliable, flexible architecture equipment needed

CONCLUSIONS

- DRAMs drive silicon device innovations and lowcost/high volume manufacturing
- ASICs drive design automation, multilevel interconnect technology, and flexible manufacturing
- Evolving synergy between memory (especially SRAMs) and ASIC processes
- Equipment design needs to be modular, highly reliable, and offer a "systems solution" to IC manufacturing
- Equipment and processes need to offer "open systems architecture"

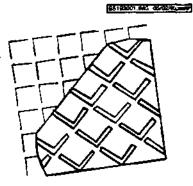
85271017 MIG 05/10/80 SHA



Dataquest

The Dun & Bradstreet Corporation

Dataquest's Annual SEMICON/West Seminar May 24, 1989



A COMPARISON OF JAPANESE AND U.S. FABS

MARK T. REAGAN

Industry Analyst
Semiconductor Equipment and Materials Service
Dataquest Incorporated

AGENDA

- Current capacity analysis
- New fabs and 200mm-wafer activity
- Market response strategies

5193003 IMG | 05/09/90/ree

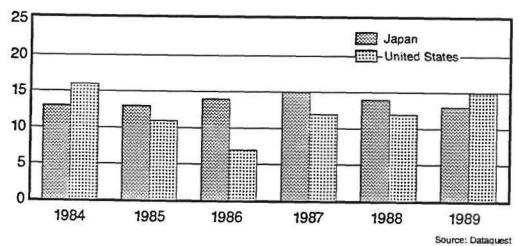
AGENDA

• Current capacity analysis

ESTIMATED SILICON PILOT AND PRODUCTION LINES

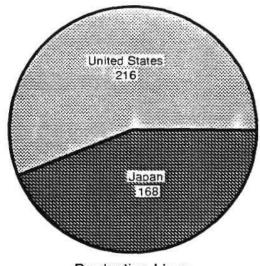
On-Shore Only

Number of Fab Lines



B5193007 MG 05/00/80 HAR

SILICON-BASED FABS



Production Lines

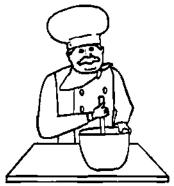
Source: Dataquest

More Fabs In United States But Japanese Fabs Are Bigger

55193000 M/G (04/04/8/ ma)

PRODUCT MIX

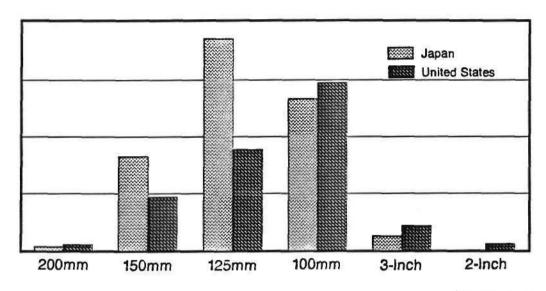
	Memory	MPU	Logic	ASIC	Other
Japan	39%	7%	6%	14%	34%
United States	25%	14%	8%	26%	27%
		_		Sout	ce: Dataquest



85193010,84G 05/09/9/1999

SILICON PILOT AND PRODUCTION LINES

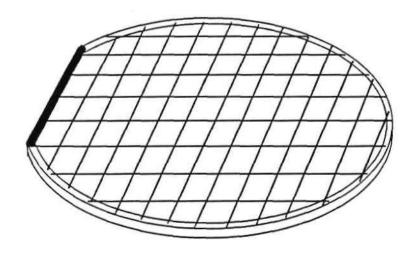
Monthly Capacity by Wafer Size



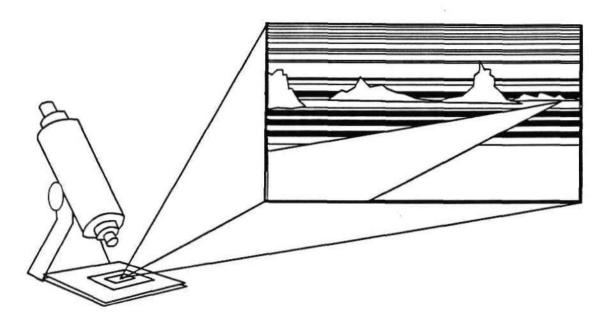
Source: Dataquest

B5193011.BMG 05/09/8/: res

WAFER SIZE



LINE GEOMETRIES



85193013.MG 05/09/8/ ma

MICRON MIX

	≤1µ	≤1.5µ	≤2.0µ	≤2.5µ	≤3µ	≥3µ
Japan	26%	33%	27%	0	10%	4%
United States	18%	33%	23%	4%	12%	12%
					Source	e: Dataquest



AGENDA

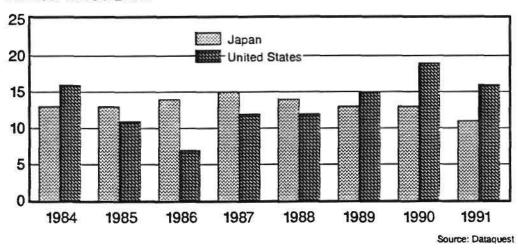
- · Current capacity analysis
- · New fabs and 200mm-wafer activity

B5193014.8AG 05A09/8// res

ESTIMATED SILICON PILOT AND PRODUCTION LINES

Onshore Only

Number of Fab Lines



8-INCH PILOT AND PRODUCTION LINES

	Japan	United States
1987 1988	NEC, Sagamihara IBM, Yasu Works	IBM, Burlington IBM, Burlington
1989	Fujitsu, Mie Tl, Hiji Plant	TI, Dallas IBM, E. Fishkill IBM, Burlington
1990	Fujitsu, Iwate Hitachi, Musashi IBM, Yasu Works NEC, Sagamihara TI, Miho?	IBM, Burlington

5193018.IMG 06/09/89:184

8-INCH PILOT AND PRODUCTION LINES

	Japan	United States
1 991	NEC, Chugoku Toshiba, Oita	NEC, Roseville TI, Dallas Motorola, Oakhill? Tohoku Semiconductor?
1992 1993	NEC, Chugoku Toshiba, Oita	Intel, Rio Rancho
		Source: Dataquest

AGENDA

- Current capacity analysis
- New fabs and 200mm-wafer activity
- Market response strategies

5193017 JMG 05/09/80708

FAB CONSTRUCTION TIMETABLE

	Permits and Planning	Break Ground to Complete Shell	Install Clean Room and Equipment	Turn On to Full Production
Japan	1 Year	7 Months	7 Months	6 to 9 Months
United States	5 Months	11 Months	11 Months	1 to 1 1/4 Years
			•	Source: Dataquest

TWO APPROACHES TO BUILDING A FAB

Japan

- One-step shopping for architecture and engineering
- Established relationships among owner, contractor, and subcontractors
- Very little bidding

United States

- Hire a person to act as a contractor
- Contractor uses bidding system
- Company may not have the same subcontractors building all fabs

(Continued)

6193019 MAG 05/90/60 res

TWO APPROACHES TO BUILDING A FAB

Japan

- Less friction between subcontractors; teamwork
- Ergonomic coordination
- Design and planning is completed before breaking ground
- Changes usually are not allowed after ground is broken

United States

- Political friction
- Get in each other's way
- Design as you build
- Delays due to internal conflicts and changes after the fact

(Continued)

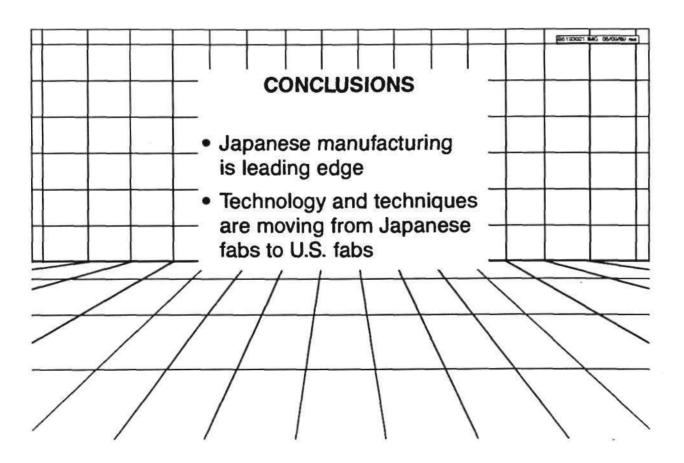
TWO APPROACHES TO BUILDING A FAB

Japan

- Contractor is responsible from design to installation of equipment
- Contractor guarantees operating performance and equipment installation schedule

United States

- Contractor usually not involved in the whole process
- Subcontractors point fingers at each other

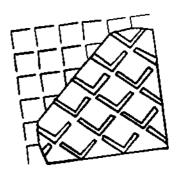


Dataquest

a company of The Dun & Bradstreet Corporation

HES SOOL M'S. OP COMO STALL

Dataquest's Annual SEMICON/West Seminar May 24, 1989



CAPITAL SPENDING: STABILITY ACHIEVED

GEORGE BURNS

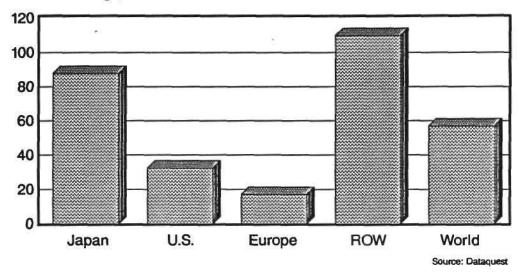
Industry Analyst
Semiconductor Equipment and Materials Service
Dataquest Incorporated

Happy days were here again (what happened last year)

85275005 IMG 05/03/89:BUR

SEMICONDUCTOR CAPITAL SPENDING GROWTH IN 1988

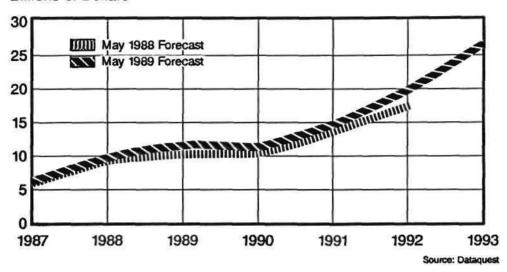
Percent Change, 1987-1988

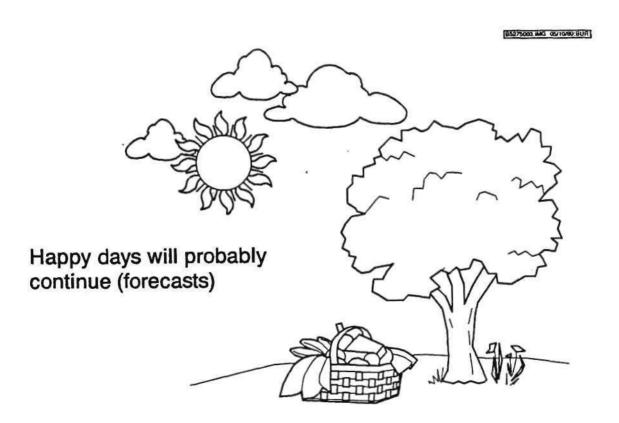


HOW DID WE DO?

Forecast Comparison

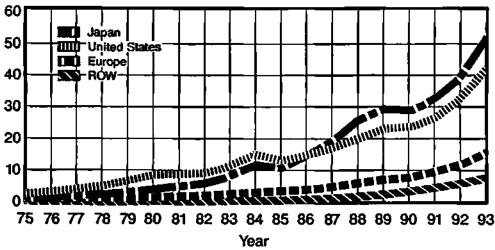
Billions of Dollars





ESTIMATED SEMICONDUCTOR PRODUCTION BY REGION

Billions of Dollars

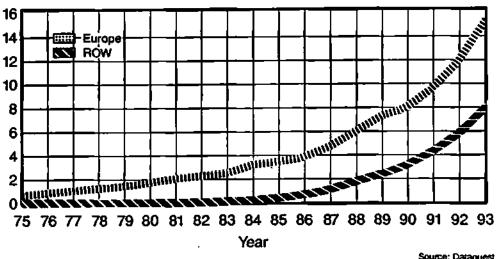


Source: Dataquest

AUS:5010.IM3 04/00/85:BUA

ESTIMATED PRODUCTION IN EUROPE AND ROW

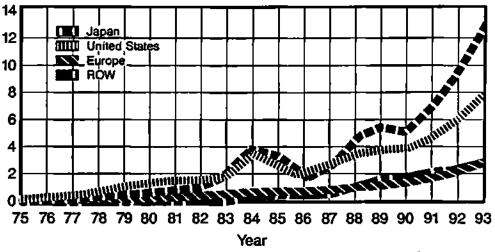
Billions of Dollars



Source: Dataquest

ESTIMATED CAPITAL SPENDING BY REGION

Billions of Dollars



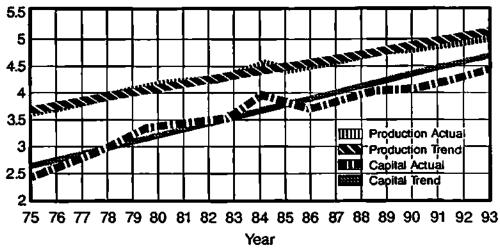
Source: Dataquest

88275020 MG 06/00MG BUA

CAPITAL SPENDING AND PRODUCTION

Actual vs. Trend

Log (Capital Spending and Production)



Source: Dataquest

ROW GROWTH PLANS

Taiwan

- Hualon
- TSMC
- UMC
- Winbond

SETS OF SALE OF SERVICES

ROW GROWTH PLANS

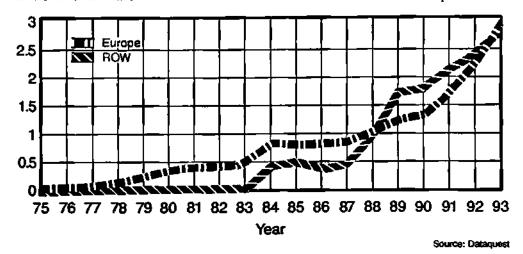
Offshore Investment

- Chartered Semiconductor
- Motorola
- SGS/Thomson
- Sony
- Vitelic

ESTIMATED CAPITAL SPENDING IN ROW AND EUROPE

Closing the Gap

Billions of Dollars



5276411.WG 05/0949-BUR

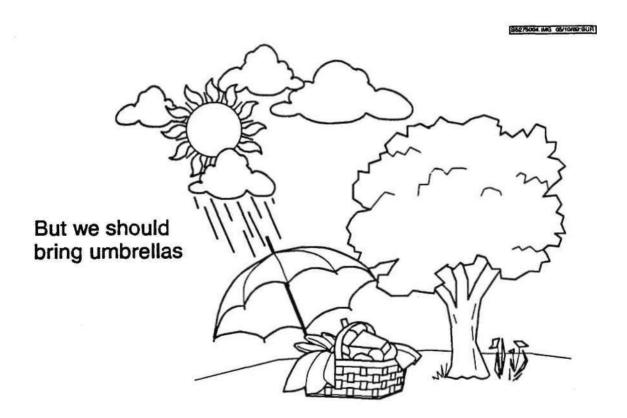
ROW GROWTH PLANS

Korea

- Goldstar
- Hyundai
- Samsung

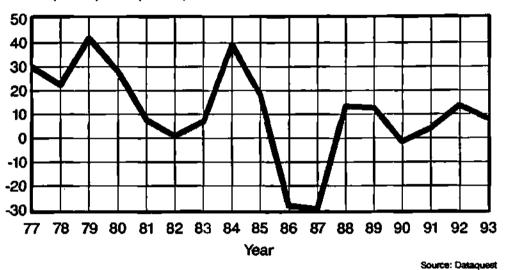
EUROPE 1992

- Production increase of \$1 billion
- Fujitsu
- Hitachi
- Texas Instruments
- Toshiba
- ?????



ESTIMATED CAGRS OF SEMICONDUCTOR REVENUE AND CAPITAL SPENDING

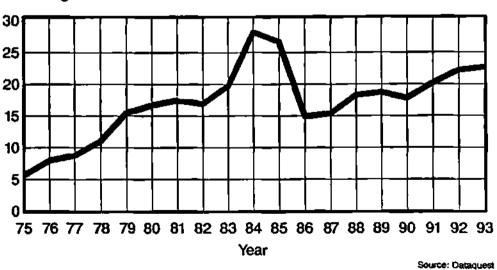
CAGR (CAPX) less (CAGR) Revenue



5275007.JMG 05/03/89 BUR

ESTIMATED CAPITAL SPENDING AS A PERCENT OF REVENUE

Percentage of Revenue

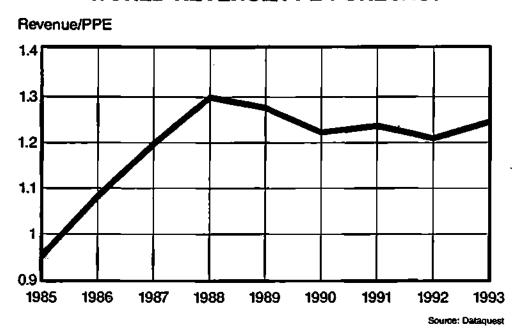


HIGHER CAPITAL SPENDING/REVENUE

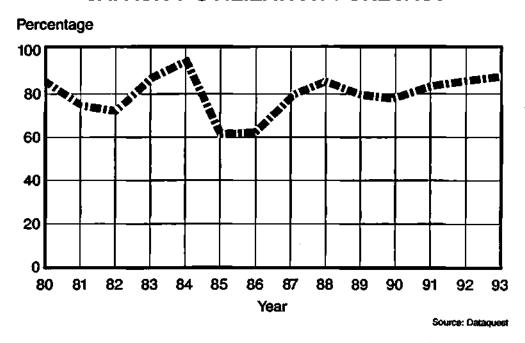
- New technologies to master
- Increased equipment cost
- · Increased fab costs

5275019.1MG 05/00/99.BUR

WORLD REVENUE/PPE FORECAST



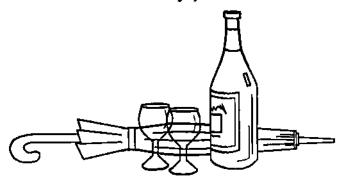
CAPACITY UTILIZATION FORECAST



BAETSOON AND GENTONED BUR

CONCLUSIONS

- Capital equipment cycles are becoming smoother
- However, potential exists for overcapacity in 1994 (keep your umbrella handy!)

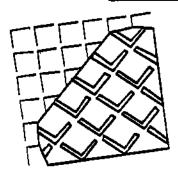


Dataquest

a company of The Dun & Bradstreet Corporation

MESSOT AND 051040-54A

Dataquest's Annual SEMICON/West Seminar May 24, 1989



WAFER FAB EQUIPMENT INDUSTRY STATUS 1989

JOSEPH GRENIER

Director
Semiconductor Equipment and Materials Service
Dataquest Incorporated

WORLDWIDE WAFER FAB EQUIPMENT MARKET

(Millions of Dollars)

1987 \$3,158 1988 \$4,773 Growth 51%

Source: Dataquest

ERSONS WEE HALDRESCHE

REGIONAL WAFER FAB EQUIPMENT MARKET

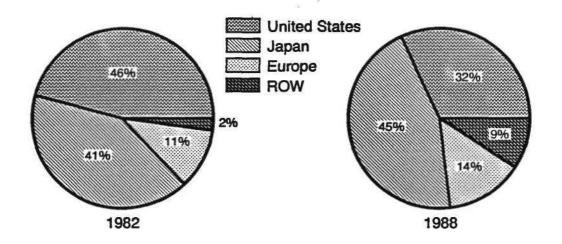
(Millions of Dollars)

	1988	1988 Growth	1988 Share
Japan	\$2,150	64%	45%
United States	1,545	42%	32
Europe	662	25%	14
ROW	416	81%	9
	\$4,773	51%	100%

Source: Dataquest

WAFER FAB EQUIPMENT MARKET

1982 versus 1988



Source: Dataquest

5323006JMG 06/10/89:GRE

WAFER FAB EQUIPMENT COMPANIES WORLDWIDE REVENUE

(Millions of Dollars)

Companies by Rank	1988 Percent of Revenue
1-10	52.2%
11-20	18.0
21-30	9.4
31-165	20.4
	100.0%
	Source: Dataquest

WAFER FAB EQUIPMENT COMPANIES

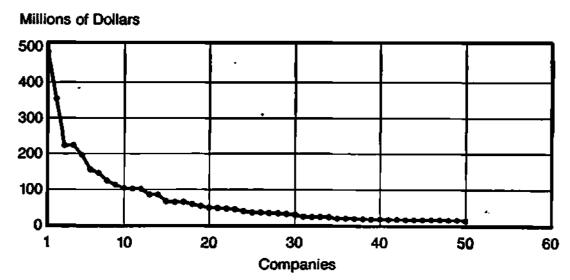
- >60% of the companies had revenue <\$10M in 1988
- 12 companies had >\$100M in 1988; only 4 did in 1986
- These 12 companies accounted for 57% of revenue
- 18% of the companies provided 80% of the revenue
- Concentration of power in wafer fab equipment industry

Source: Dataquest

192307 JUNE 1071040-0FUE

WAFER FAB EQUIPMENT

Concentration of Power



Source: Dataquest

WAFER FAB EQUIPMENT

1988 High-Growth Equipment Segments

Segment	Worldwide Growth	Japanese Growth	United States Growth
implant	100%	145%	75%
Dry Etch	96%	144%	68%
CD/Wafer Inspection	78%	67%	82%
CVD	76%	98%	66%
Steppers	76%	99%	49%
Dry Strip	73%	93%	40%
Track	52%	94%	28%
Diffusion	51%	39%	120%
All Segments	77%	101%	62%

Source: Dataquest

SESON IN OUR OWNERS

STEPPERS 1988

(Units)

**	1988 Grow	
Japan	92%	
United States	21%	
Europe	15%	
ROW	83%	
Total World	55%	

- Japan has largest installed base of steppers
- ROW installed 40% more steppers than Europe
- Japan/ROW accounted for > 60% of stepper market

Source: Dataquest

STEPPERS 1988

Concentration of Power Market Share (Units)

Nikon	53%
Canon	18%
GCA	10%
ASM Lithography	6%

Source: Dataquest

CARSON HAS DEVIDED BREE

LITHOGRAPHY EVENTS IN 1988

- Introduction of high-N.A. g-line lenses for 0.65-micron resolution
- At SPIE conference, g- and i-liners talked about 0.5-micron resolution
- Continued improvements in excimer laser steppers
- Perkin-Elmer announced Micrascan
- What's an X-ray?

CHEMICAL VAPOR DEPOSITION 1988

	Unit Growth	ASP(\$K)
Tube CVD	10%	\$215
Nontube CVD	67%	\$650

- 80% of the CVD market revenue growth in 1988 was due to nontube DVD
- Nontube CVD accounted for 64% of CVD market in 1988; 40% in 1985
- Tube CVD units have declined by 40%; revenue has increased by only 16%

Source: Dataquest

ASSESSMENT OF THE GRE

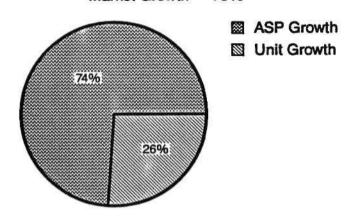
CHEMICAL VAPOR DEPOSITION 1988

Concentration of Power Market Share (Revenue)

Nontube Reactors		Tube Reactors		
Applied Materials	32%	ASM International	47%	
Watkins-Johnson	13%	BTU/Bruce	9%	
Genus	12%	Tokyo Electron	7%	
Novellus	8%			

CD/WAFER INSPECTION 1988

Market Growth = 78%

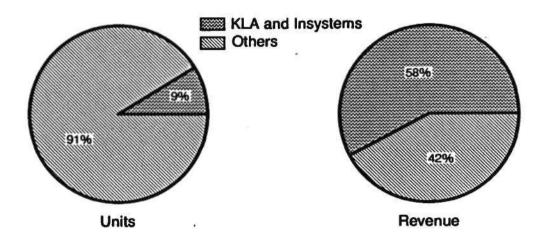


- Emphasis on submicron measurement capability
- · Emergence of automated defect detection systems
- · Result is very high ASP systems

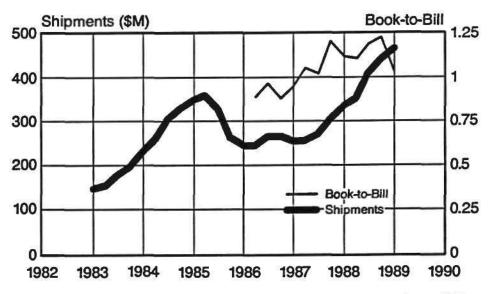
Source: Dataquest

85323015.MG 05/10/89:GFE

AUTOMATED WAFER INSPECTION TOOLS 1988



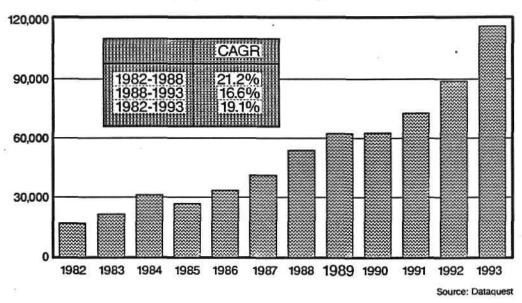
EQUIPMENT BUSINESS INDEX AND BOOK-TO-BILL



Source: SEMI Dataquest

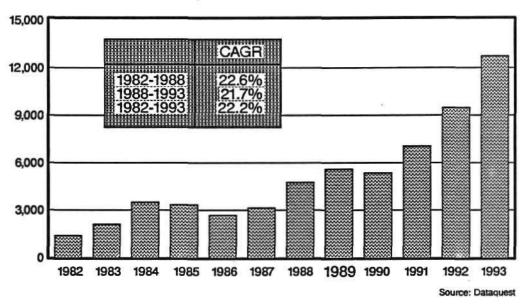
85323017 IMG 05/10/89:GRE

SEMICONDUCTOR PRODUCTION



WAFER FAB EQUIPMENT

(Millions of Dollars)



5323019HMG 06/10/89:GRE

SUMMARY

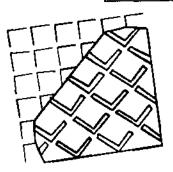
- Japan largest equipment market
- Concentration of power
- Wafer fab equipment up 18% in 1989
- Strong growth in 1991-1993

Dataquest

acompany of The Dun & Bradstreet Corporation

85137001 MG 05/02/80 ww

Dataquest's Annual SEMICON/West Seminar May 24, 1989



SILICON WAFERS: EXISTING MARKETS AND FUTURE OPPORTUNITIES

PEGGY MARIE WOOD, Ph.D.

Industry Analyst
Semiconductor Equipment and Materials Service
Dataquest Incorporated

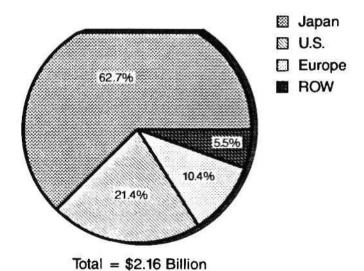
EXISTING MARKETS -- SILICON AND EPITAXIAL WAFERS

Agenda

- Market overview
- · Wafer pricing update
- · Looking ahead at 8"
- · Acquisitions revisited

85137000 IMG 04/25/RJ W(X)

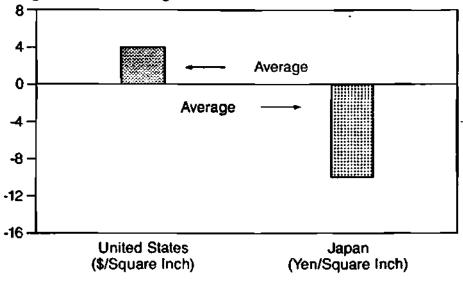
1988 MERCHANT SILICON AND EPITAXIAL WAFER MARKET BY REGION



WAFER PRICING UPDATE

Polished CZ Wafers





Source: Dataquest

5137006 (MG | 64/27/80 WUX)

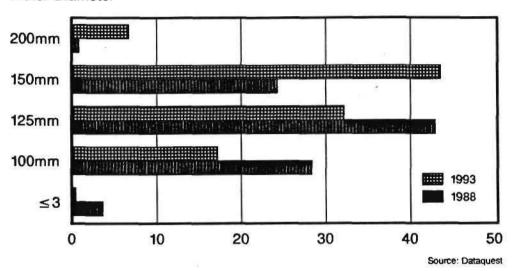
LOOKING AHEAD TO 8"

- 8" fab activity
- Wafer size forecast

WORLDWIDE WAFER SIZE DEMAND

Percent Square Inches

Wafer Diameter



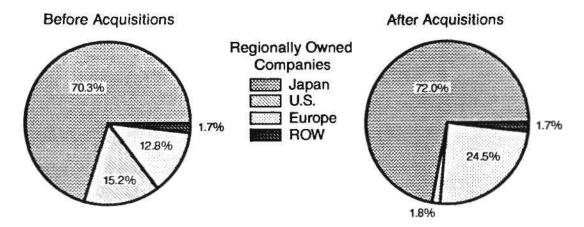
5137008 IMG 04/27/80 WOL)

SILICON ACQUISITIONS REVISITED

Year	Company		Acquired By
1988	Monsanto Electonic Materials Company	-	Huels AG
1988	Cincinnati Milacron	•	Osaka Titanium Company
1987	Dynamit Nobel Silicon	-	Huels AG
1986	U.S. Semiconductor		Osaka Titanium Company
1986	Siltec Corporation		Mitsubishi Metal
1985	NBK Corporation	•	Kawasaki Steel

SHIFTING SHARE IMPACT OF RECENT ACQUISITIONS

1988 = \$2.16 Billion



Source: Dataquest

5137010 IMG 04/27/89:WOO

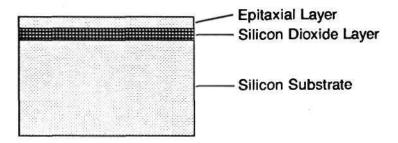
FUTURE OPPORTUNITIES -- SILICON ON INSULATOR

Agenda

- · Advantages and applications
- SOI suppliers
- Technology overview
- Outlook

WHAT IS SOI?

SOI (silicon on insulator) wafers consist of a thin epitaxial layer of silicon on an insulating layer of silicon dioxide over a silicon substrate.



5137012 IMG 06/02/89 WOO

SOI ADVANTAGES

- High packing density/freedom from latch-up
- High-speed operation
- Inherent radiation hardness
- High-temperature operation
- High-voltage capability
- Standard silicon processing

SOI APPLICATIONS

Military, aerospace, automotive, and telecommunications

- Fabricated devices include:
 - 3-GHz ring oscillator (Hughes)
 - Linear ICs (Silicon General)
 - 16K/64K CMOS SRAMs (TI)

\$137014 IMG 05/02/80 WOO

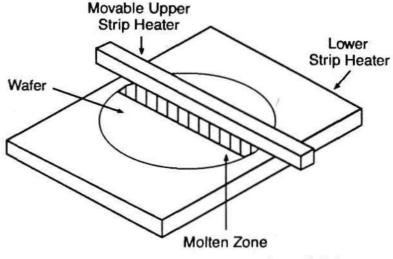
SOI WAFER SUPPLIERS

Company	SOI Wafer Technology	Initial Technology Development
Applied Electron Corporation	EBZMR	Colorado State Univ., Fort Collins
Kopin Corporation	ISE/ZMR	MIT Lincoln Labs
Ibis Technology Corporation	SIMOX	Eaton Corporation
Spire Corporation	SIMOX	Spire, Texas Instruments

EBZMR = Electron-Beam Zone Melt Recrystallization ISE/ZMR = Isolated Silicon Epitaxy/Zone Melt Recrystallization SIMOX = Separation by IMplantation of OXygen

SOI TECHNOLOGY OVERVIEW

Isolated Silicon Epitaxy (ZMR)

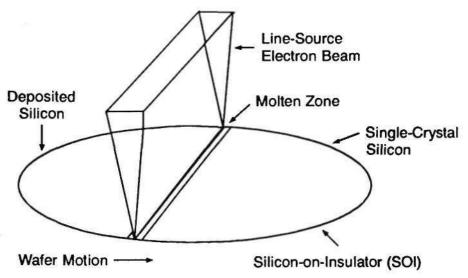


Source: Kopin Corporation Dataquest

B5137016 MAG 05/02/RJ WOO

SOI TECHNOLOGY OVERVIEW

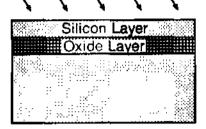
Electron-Beam ZMR



Source: Applied Electron Corporation Dataquest

SOI TECHNOLOGY OVERVIEW SIMOX

O+ 200 kev 1.8 x 1018 ions/cm2



Source: Ibls Technology Corporation Dataquest

5137018.MG 05/02/8019(V)

SOI OUTLOOK

Moving Down the Learning Curve

- Lower defect densities
- Lower wafer prices

SOI OUTLOOK

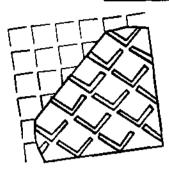
Moving Down the Learning Curve

- Lower defect densities
- Lower wafer prices



86184020 MG 05/10/10 SHA

Dataquest's Annual SEMICON/West Seminar May 24, 1989



JAPANESE SEMICONDUCTOR EQUIPMENT MARKET STATUS

KAZ HAYASHI

Industry Analyst
Semiconductor Equipment and Materials Service
Dataquest Japan Limited

AGENDA

- Semiconductor production analysis and forecast
- · Capital spending analysis and forecast
- Fabrication equipment demand analysis
 - Lithography
 - Etch and clean
 - Deposition
 - Diffusion and rapid thermal processing (RTP)
 - Implantation
- Summary

5194002194G 06/12/69:HAY

ESTIMATED JAPANESE SEMICONDUCTOR PRODUCTION AND CAPITAL SPENDING 1984-1988

(Millions of Dollars)

	1984	1985	<u> 1986</u>	1987	1988
Japanese Semiconductor Production	\$12,007	\$10,651	\$14,686	\$18,958	\$25,90 3
Capital Spending	\$3,900	\$3,336	\$1,850	\$2,432	\$4,568

ESTIMATED JAPANESE SEMICONDUCTOR PRODUCTION AND CAPITAL SPENDING 1989-1993

(Millions of Dollars)

	1989	1990	1991	1992	1993	CAGR 1988-93
Japanese Semiconductor Production	\$29,632	\$28,492	\$32,537	\$39,270	\$51,536	15%
Capital Spending	\$5,488	\$4,972	\$6,915	\$9,439		23%

8184004 IMG 05/12/89 IAY

Source: Dataquest

ESTIMATED JAPANESE COMPANY CAPITAL SPENDING

(Millions of Dollars)

Calendar Year

Company	1980	1981	1982	1983	1984
Fujitsu	\$111				\$ 48 5
Hitachi	93				506
Matsushita	89				464
Mitsubishi	36				274
NEC	133				544
Oki	53				110
Sanyo	36				135
Sharp	38				110
Toshiba	49				574
Others	o				468
Total	\$63 8	\$834	\$921	\$1,698	\$3,671

ESTIMATED JAPANESE COMPANY CAPITAL SPENDING

(Millions of Dollars)

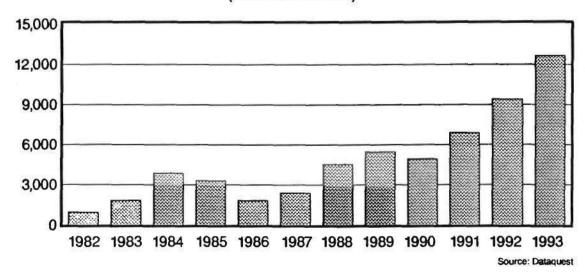
Calendar Year

Company	1984	1985	1986	1987	1988	1989	% Change 1988-1989
Fujitsu	A	S		11-11-11	\$ 462	\$ 462	0%
Hitachi					500	538	8%
Matsushita					385	462	20%
Mitsubishi					308	385	25%
NEC					423	538	27%
Oki					285	308	8%
Sanyo					223	269	21%
Sharp					269	346	29%
Toshiba					615	615	0%
Others					1,015	1,508	48%
Total	\$3,671	\$3,219	\$1,766	\$2,345	\$4,485	\$5,431	21%

Source: Dataquest

(85184013 MAG 05/15/80:HAY)

ESTIMATED JAPANESE CAPITAL SPENDING



JAPANESE WAFER FAB EQUIPMENT MARKET

(Millions of Dollars)

1982 1988 CAGR \$580 \$2,150 24.5%

\$1\$4007.IMG 66/12/00:HAY

JAPANESE FABRICATION EQUIPMENT MARKET

	1982	1988	CAGR 1982-1988
Etch and Clean	\$ 76	\$ 396	31.7%
Deposition	121	414	22.8%
Diffusion and RTP Implantation	48	129	18.0%
	48	220	28.9%
Total	\$293	\$1,159	25.7% Source: Dataquest

LITHOGRAPHY

(Millions of Dollars)

	1982	1988	CAGR 1982-1988
Contact/Proximity Projection Aligners Steppers Direct-Write E-Beam X-Ray	\$ 26 29 60 28 0	\$ 4 25 423 67 2	(26.8%) (2.4%) 38.6% 15.7% N/A
Automatic Photoresist Processing Equipment	<u>28</u>	120	27.5%
Total N/A = Not Available	\$171	\$641	24.7%

Source: Dataquest

\$184000 IMG 65/12/80 HAY

ETCH AND CLEAN

	1982	1988	CAGR 1982-1988
Wet Process Dry Strip	\$27 10	\$ 92 59	22.7% 34.5%
Dry Etch	<u>42</u>	245	34.2%
Total	\$76	\$396	31.7% Source: Dataquest

DEPOSITION

(Millions of Dollars)

	1982	1988	CAGR 1982-1988
Chemical Vapor Deposition	\$ 43	\$190	28.2%
Physical Vapor Deposition	46	126	18.3%
Silicon Epitaxy	32	98	20.6%
Total	\$121	\$414	22.8% Source: Dataquest

5184011 JMS 08/12/00 HAY

DIFFUSION AND RTP

(Millions of Dollars)

	1982	1988	CAGR 1982-1988
Diffusion Rapid Thermal Processing	\$47 	\$122 	18.1% 38.4%
Total	\$48	\$129	18.0%

ION IMPLANTATION

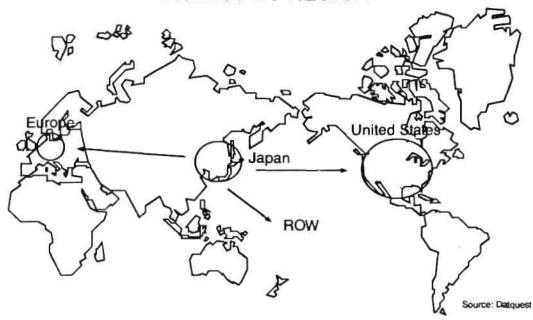
(Millions of Dollars)

	1982	1988	CAGR 1982-1988
Medium Current High Current	\$22 26	\$ 59 161	17.9% 39.4%
High Voltage	< 1	< 1	N/A
Total	\$48	\$220	28.9%
N/A = Not Applicable			

Source: Dataquest

85184014.BMG 05/15/89:hey

JAPANESE WAFER FAB PLANTS BY REGION



SUMMARY

- Will continue to increase Japanese capital spending
- Will expand Japanese market shares for semiconductor equipment worldwide
- · Will establish new fab lines worldwide